US00D823278S

(12) **United States Design Patent** (10) **Patent No.: US D823,278 S**

Ito et al. (45) **Date of Patent: ** Jul. 17, 2018**

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(54) **HEADPHONE**

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(72) Inventors: **Tomohiro Ito**, Tokyo (JP); **Yosuke Nakamura**, Tokyo (JP); **Shunsuke Shiomi**, Tokyo (JP); **Hideto Yamamoto**, Kanagawa (JP); **Yusuke Otani**, Kanagawa (JP); **Kenji Katsumata**, Chiba (JP)

(73) Assignee: **SONY CORPORATION**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/465,753**

(22) Filed: **Aug. 30, 2013**

(51) **LOC (11) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205**

(58) **Field of Classification Search**
USPC D14/205, 206, 223; 181/129, 130, 135; 379/430, 431; 381/380, 381, 374, 375,
(Continued)

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Primary Examiner — Paula Allen Greene

(74) *Attorney, Agent, or Firm* — Michael Best and Friedrich LLP

(57) **CLAIM**

The ornamental design for a headphone, as shown.

DESCRIPTION

FIG. **1** is a perspective view of a first embodiment of a headphone showing our new design;

FIG. **2** is a front elevational view thereof;

FIG. **3** is a rear elevational view thereof;

FIG. **4** is a left side elevational view thereof;

FIG. **5** is a top plan view thereof; and

FIG. **6** is a bottom plan view thereof.

FIG. **7** is a perspective view thereof wherein the headphone housing is in a first alternate position;

FIG. **8** is a perspective view thereof wherein the headphone housing is in a second alternate position;

FIG. **9** is a perspective view thereof wherein the headphone housing is in a third alternate position;

FIG. **10** is a perspective view thereof wherein the headphone housing is in a fourth alternate position;

FIG. **11** is a rear elevational view thereof wherein the headphone housing is in the first alternate position;

FIG. **12** is a rear elevational view thereof wherein the headphone housing is in the second alternate position; and

FIG. **13** is a rear elevational view thereof wherein the headphone housing is in the third alternate position.

FIG. **14** is a rear elevational view thereof wherein the headphone housing is in the fourth alternate position.

FIG. **15** is a perspective view of a second embodiment of a headphone showing our new design;

FIG. **16** is a front elevational view thereof;

FIG. **17** is a rear elevational view thereof;

FIG. **18** is a left side elevational view thereof;

FIG. **19** is a top plan view thereof; and

FIG. **20** is a bottom plan view thereof.

FIG. **21** is a perspective view thereof wherein the headphone housing is in a first alternate position;

FIG. **22** is a perspective view thereof wherein the headphone housing is in a second alternate position;

FIG. **23** is a perspective view thereof wherein the headphone housing is in a third alternate position;

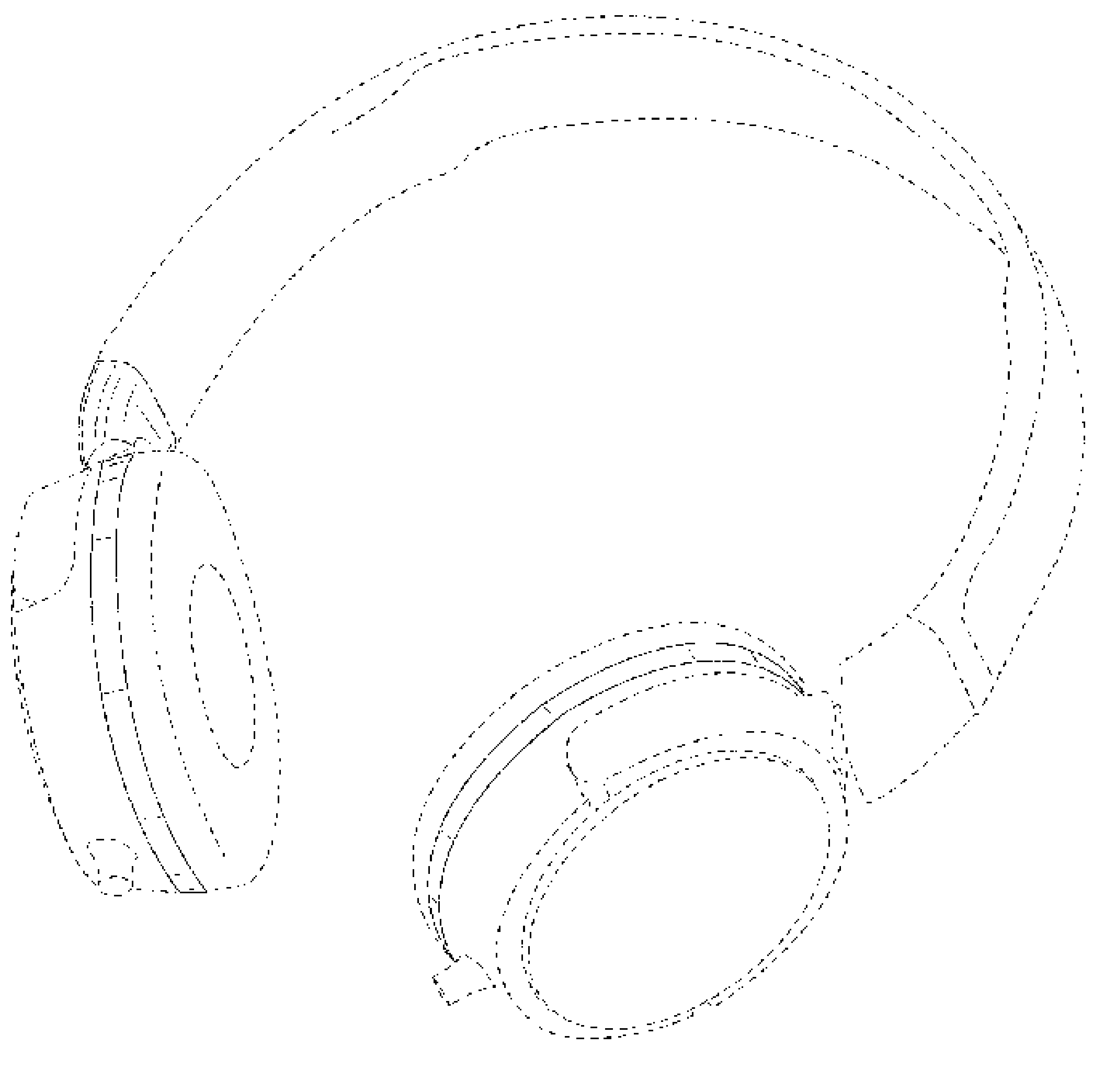
FIG. **24** is a perspective view thereof wherein the headphone housing is in a fourth alternate position;

FIG. **25** is a rear elevational view thereof wherein the headphone housing is in the first alternate position;

FIG. **26** is a rear elevational view thereof wherein the headphone housing is in the second alternate position;

FIG. **27** is a rear elevational view thereof wherein the headphone housing is in the third alternate position; and

(Continued)



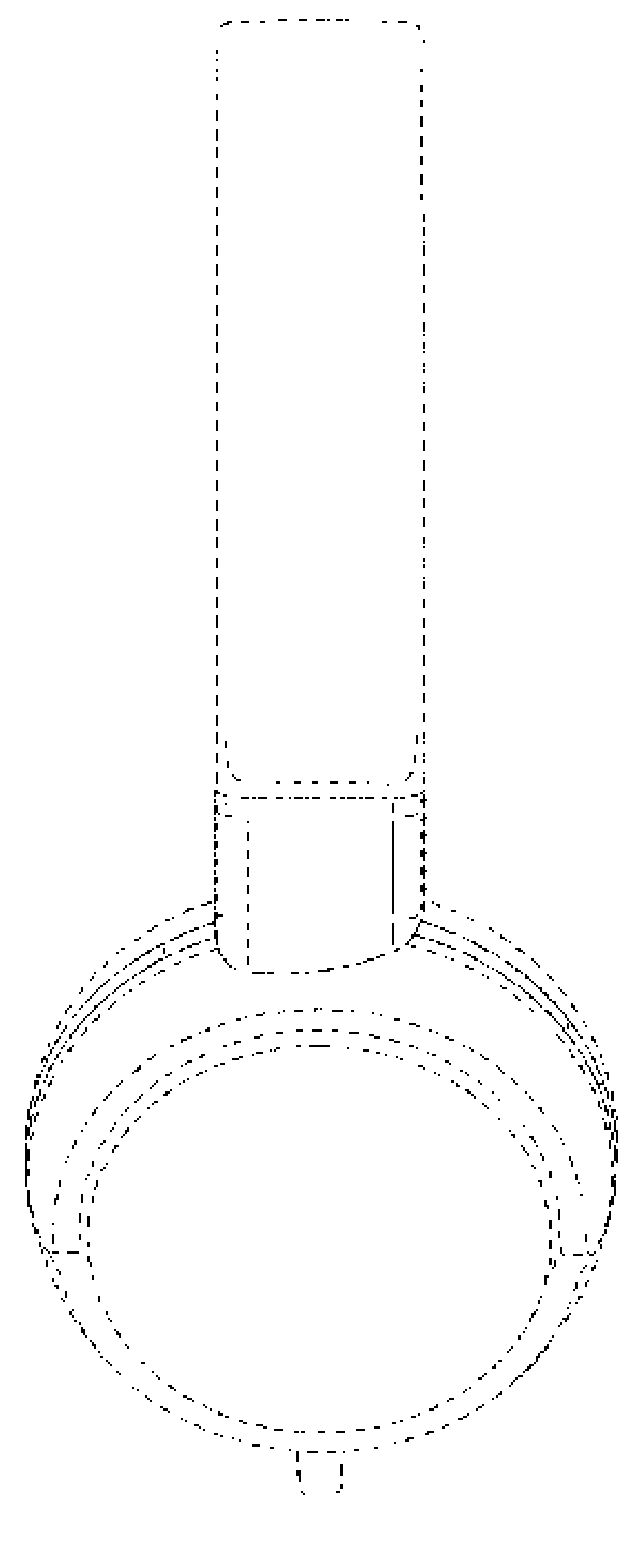


FIG. **28** is a rear elevational view thereof wherein the headphone housing is in the fourth alternate position.
FIG. **29** is a perspective view of a third embodiment of a headphone showing our new design;
FIG. **30** is a front elevational view thereof;
FIG. **31** is a rear elevational view thereof;
FIG. **32** is a left side elevational view thereof;
FIG. **33** is a top plan view thereof; and
FIG. **34** is a bottom plan view thereof.
FIG. **35** is a perspective view thereof wherein the headphone housing is in a first alternate position;
FIG. **36** is a perspective view thereof wherein the headphone housing is in a second alternate position;
FIG. **37** is a perspective view thereof wherein the headphone housing is in a third alternate position;
FIG. **38** is a perspective view thereof wherein the headphone housing is in a fourth alternate position;
FIG. **39** is a rear elevational view thereof wherein the headphone housing is in the first alternate position;
FIG. **40** is a rear elevational view thereof wherein the headphone housing is in the second alternate position;
FIG. **41** is a rear elevational view thereof wherein the headphone housing is in the third alternate position; and
FIG. **42** is a rear elevational view thereof wherein the headphone housing is in the fourth alternate position.
FIG. **43** is a right side elevational view of the embodiment of FIG. **1**;
FIG. **44** is a right side elevational view of the embodiment of FIG. **15**; and,
FIG. **45** is a right side elevational view of the embodiment of FIG. **29**.
The broken lines illustrating unclaimed portions of the headphone form no part of the claimed design. Dot-dash broken lines illustrating boundaries of the claimed design form no part of the claimed design.

1 Claim, 42 Drawing Sheets

(58) **Field of Classification Search**
USPC 381/74; 455/90.3, 575.1; D29/112; 2/209
CPC H04R 1/1066; H04R 1/1016; H04R 25/00; H04R 1/10; H04R 5/0335; H04R 5/033
See application file for complete search history.

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FIG.1

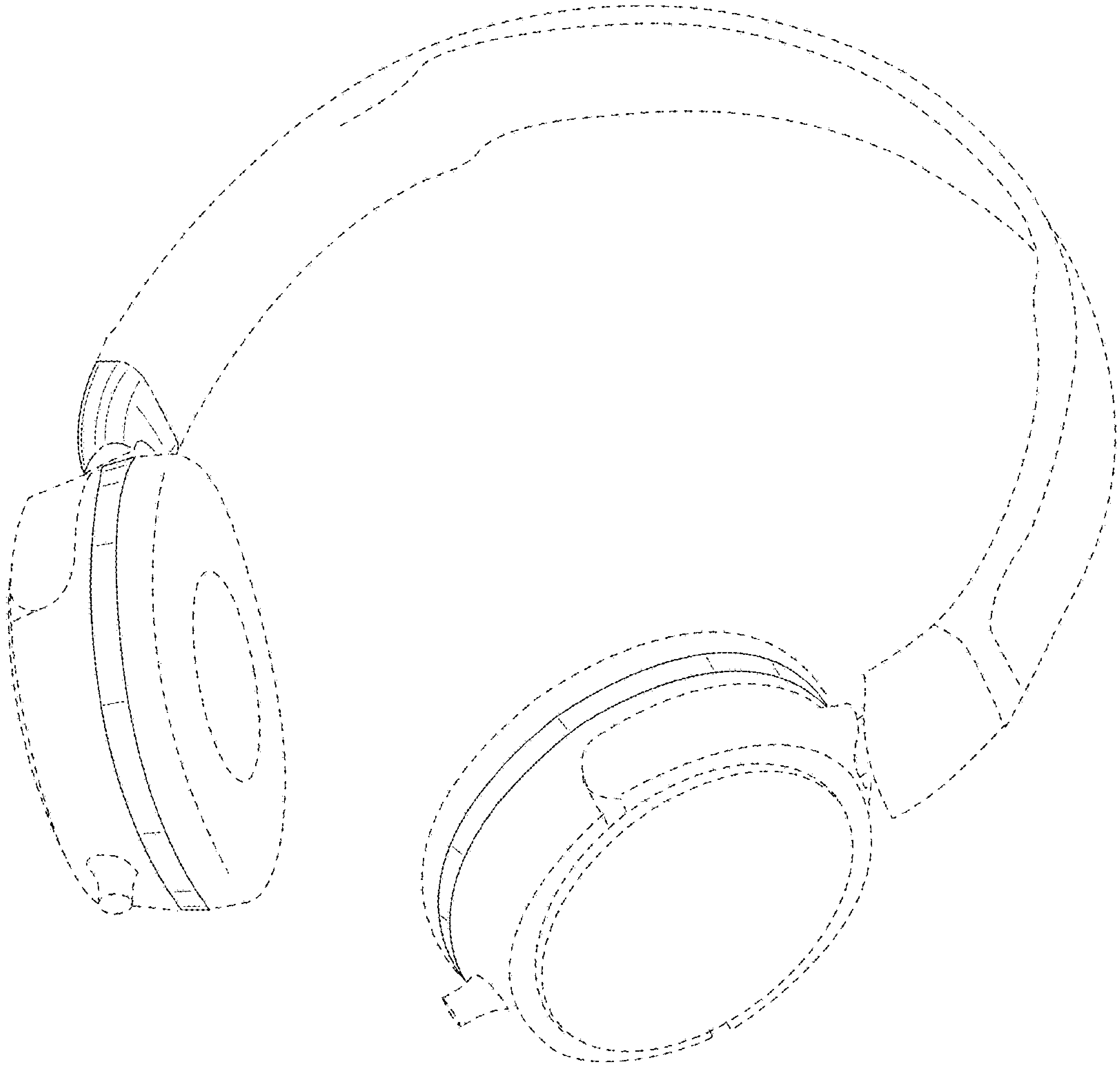
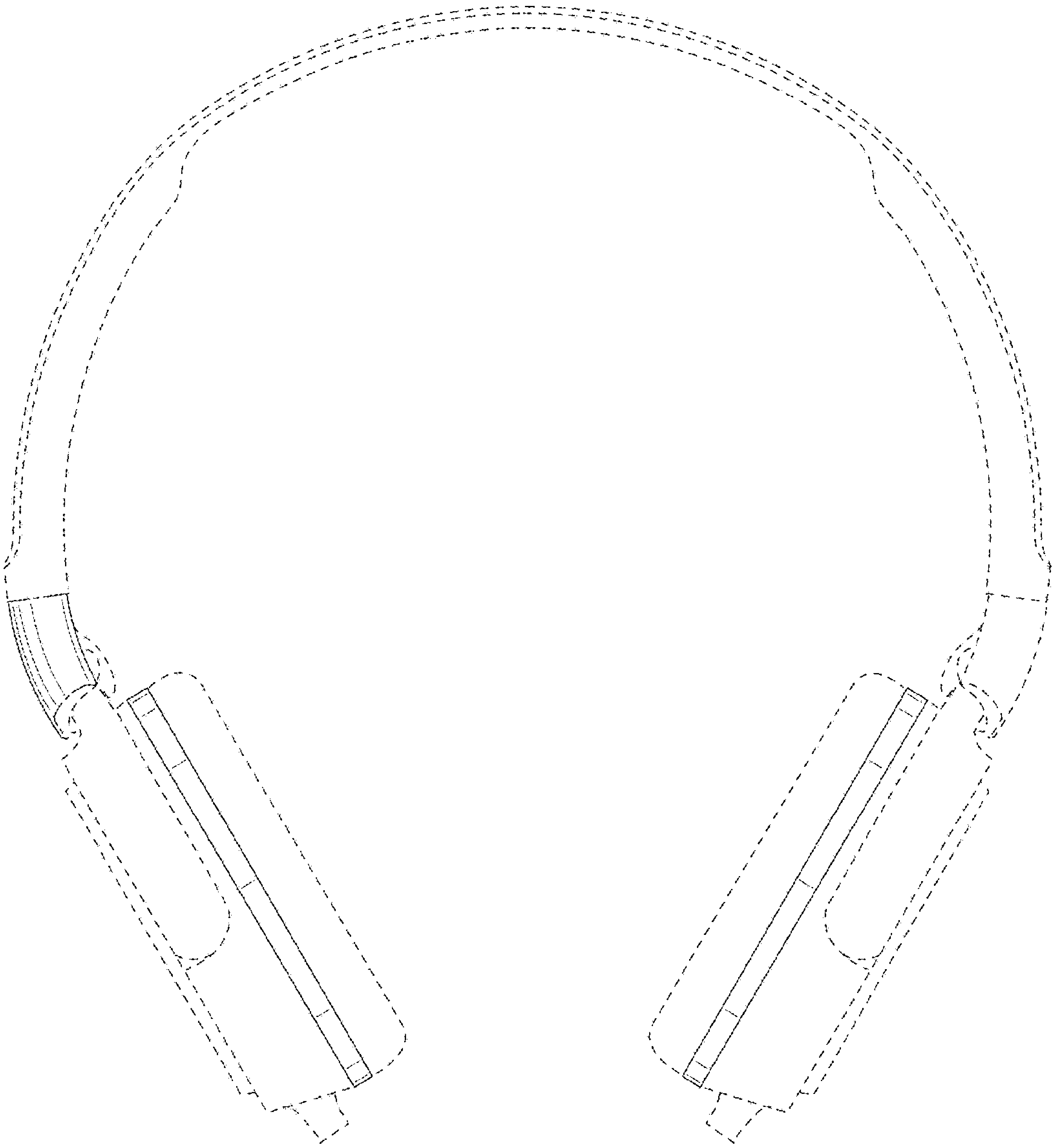


FIG.2



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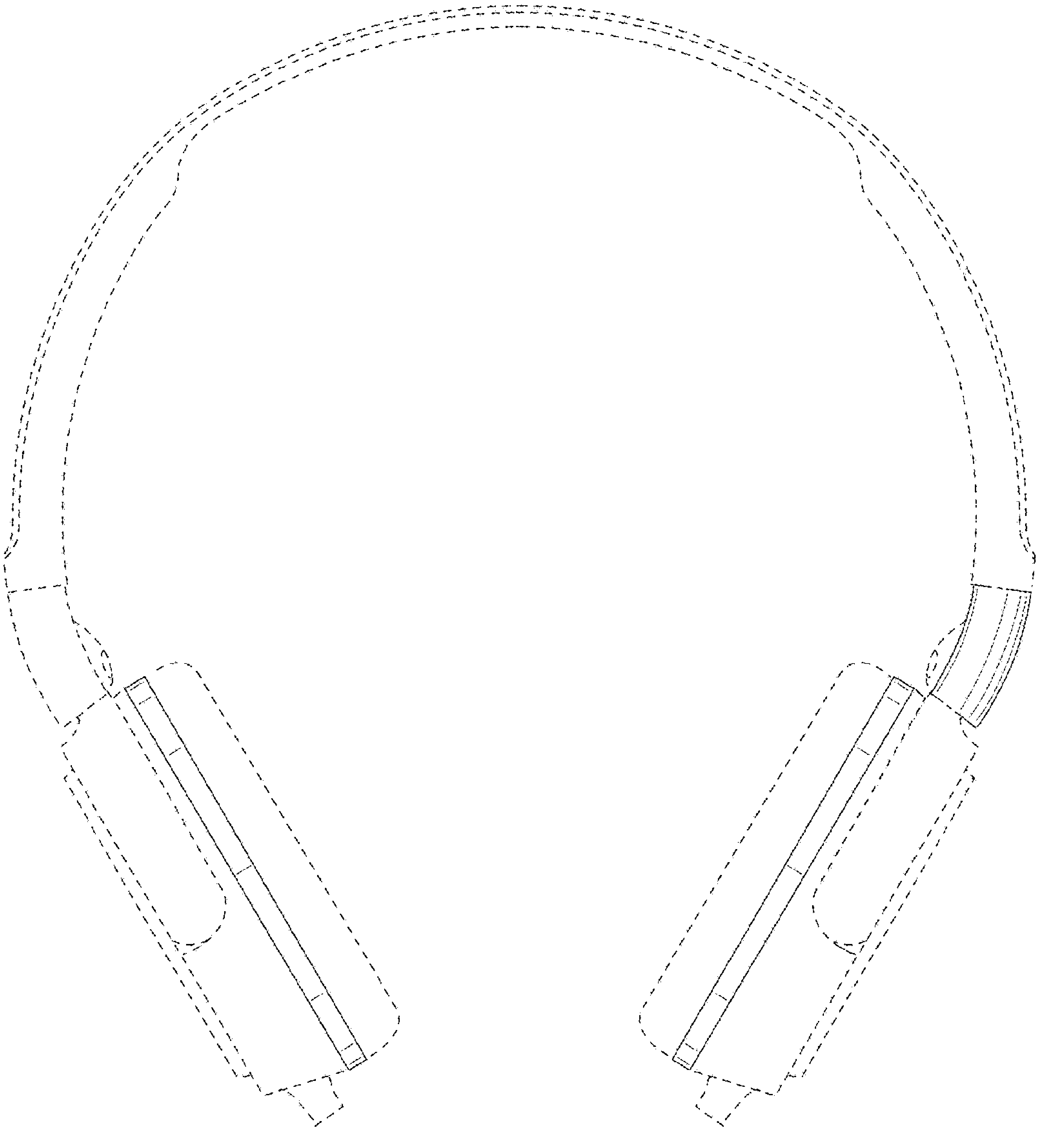

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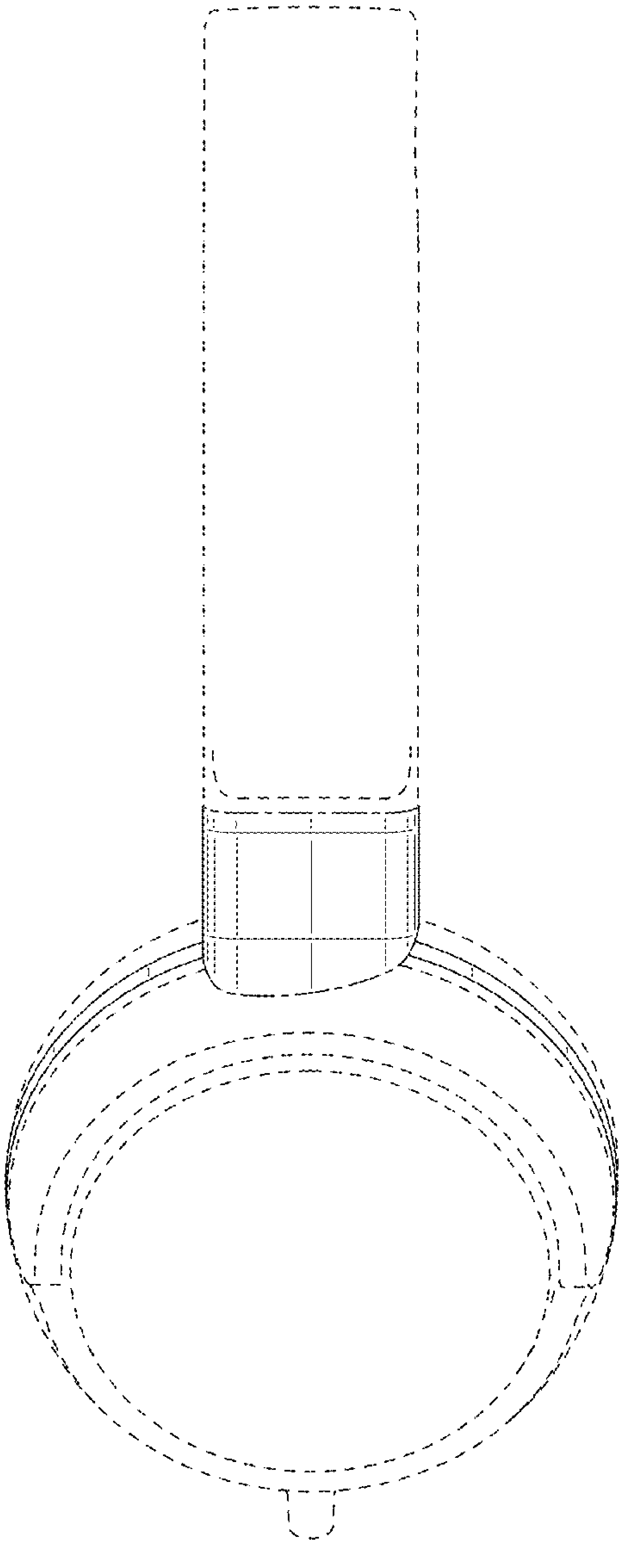


FIG.5

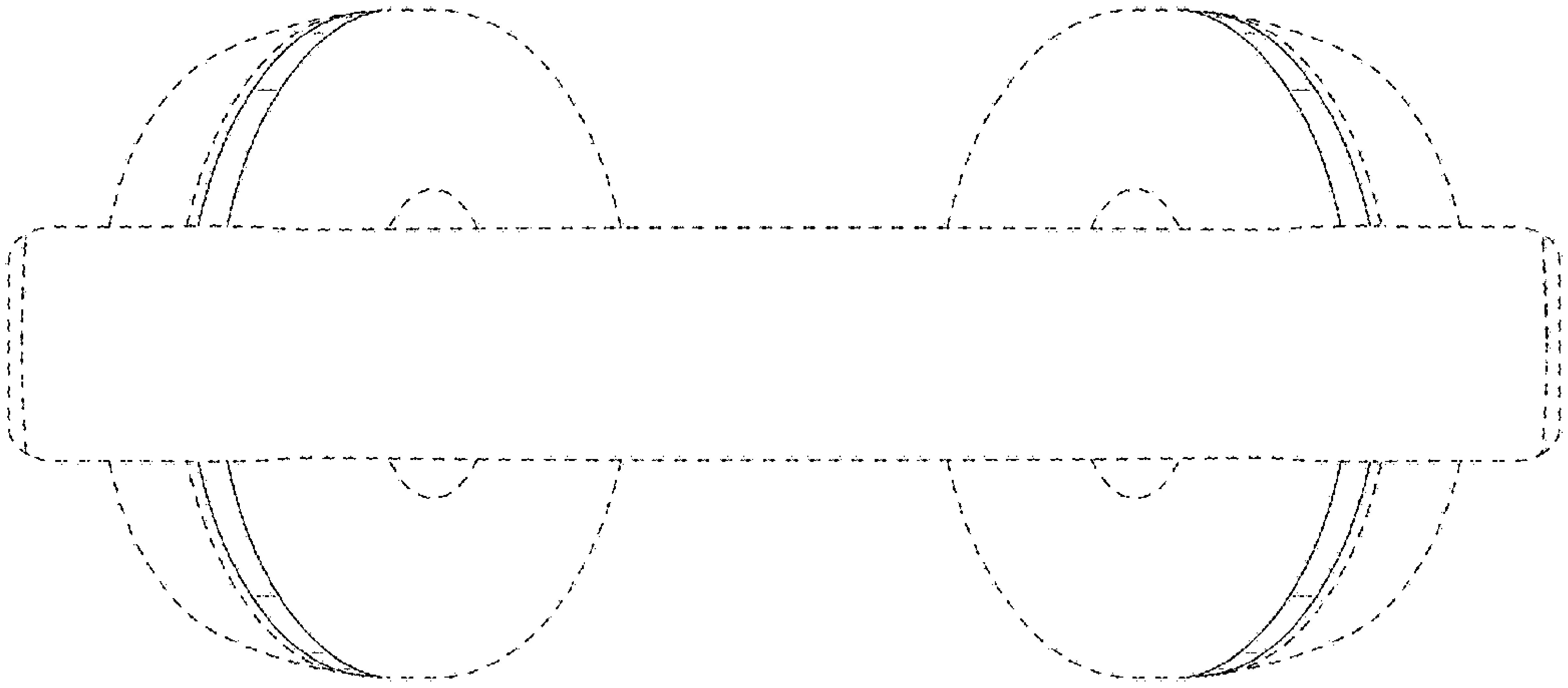
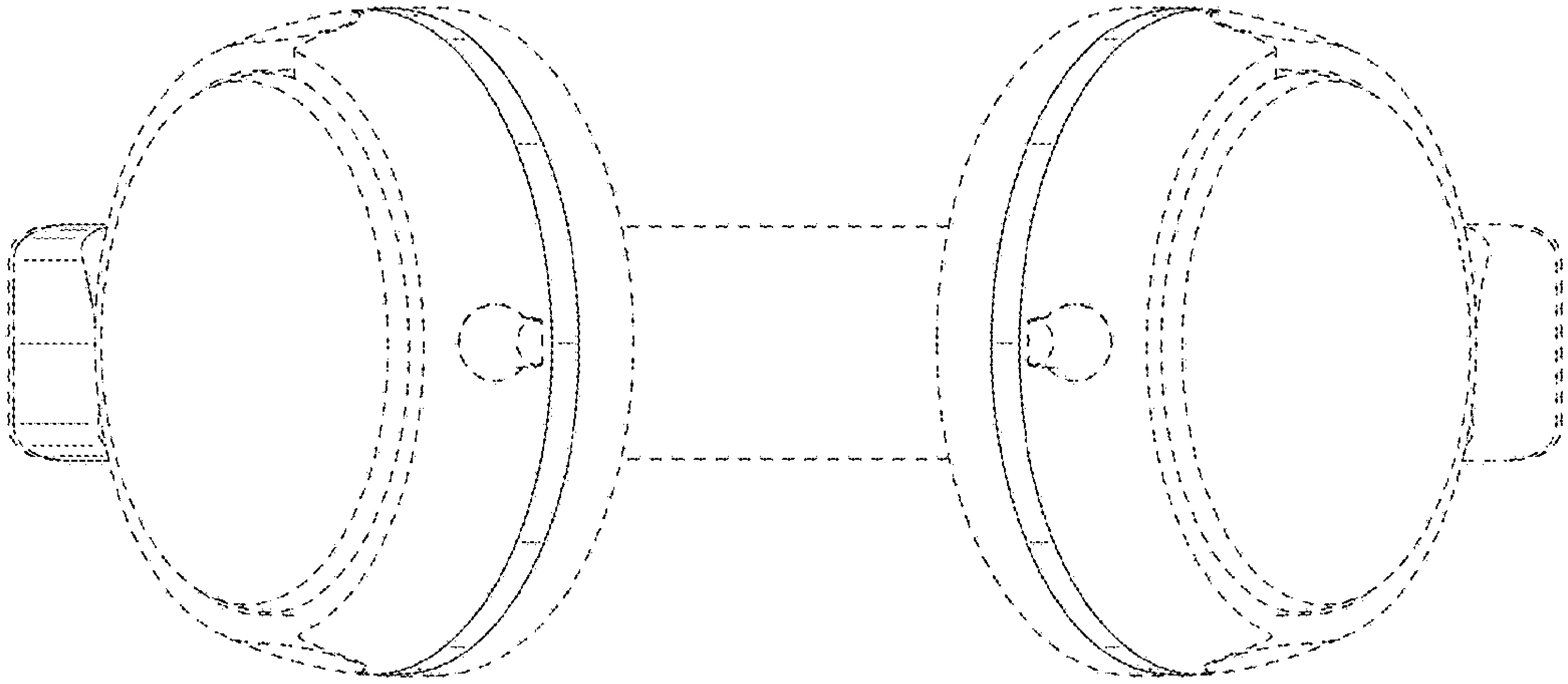


FIG.6



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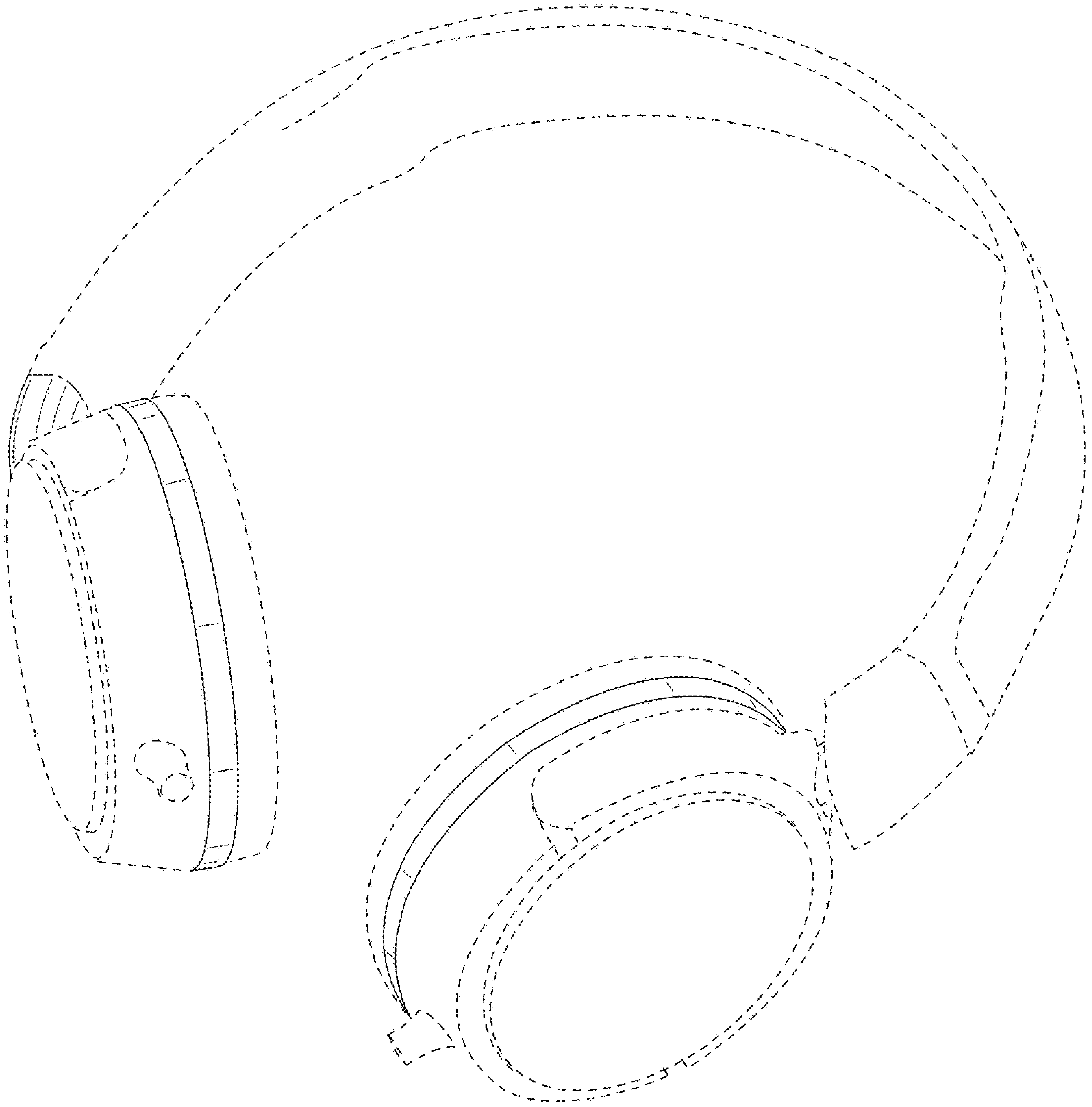

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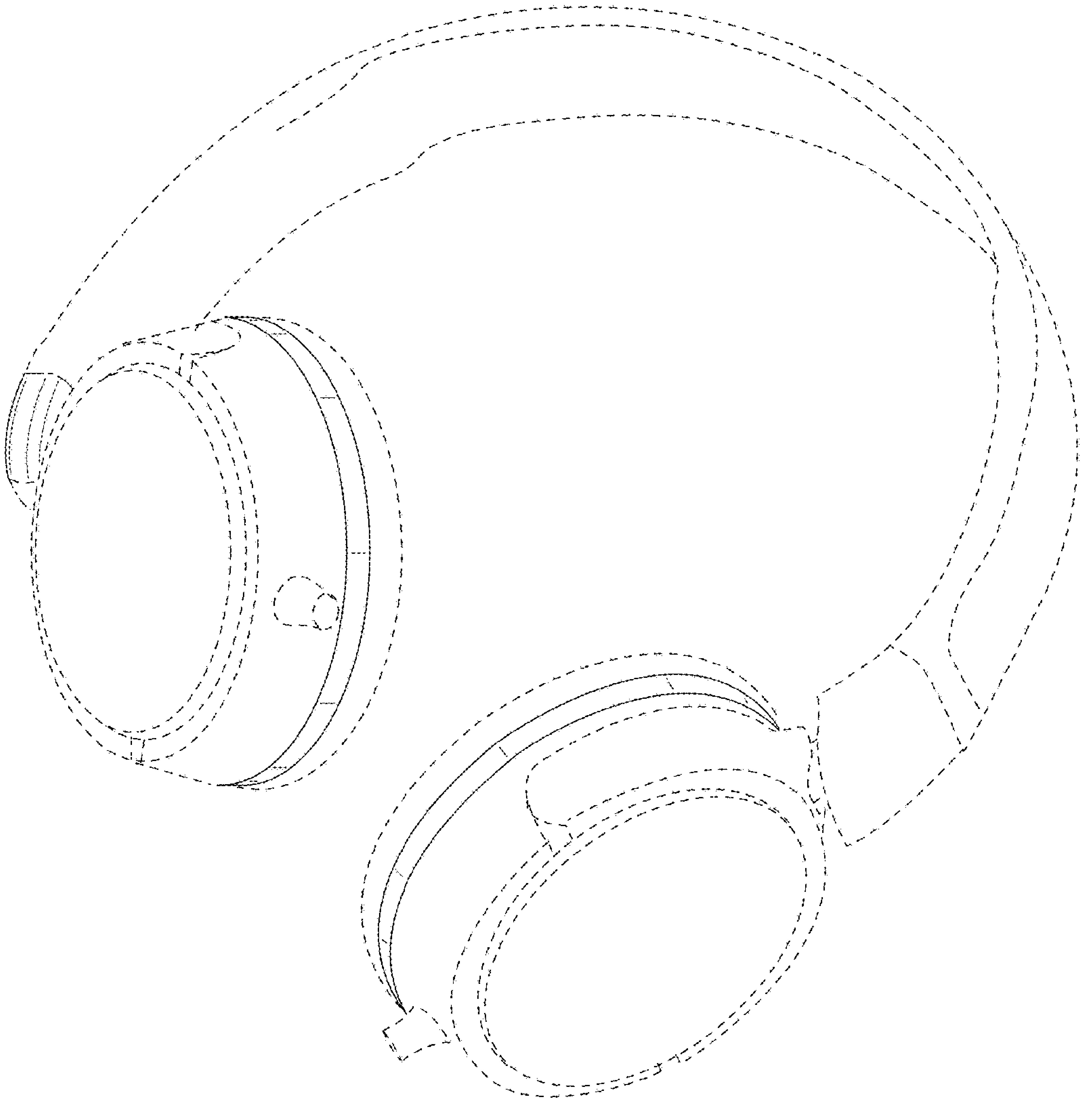
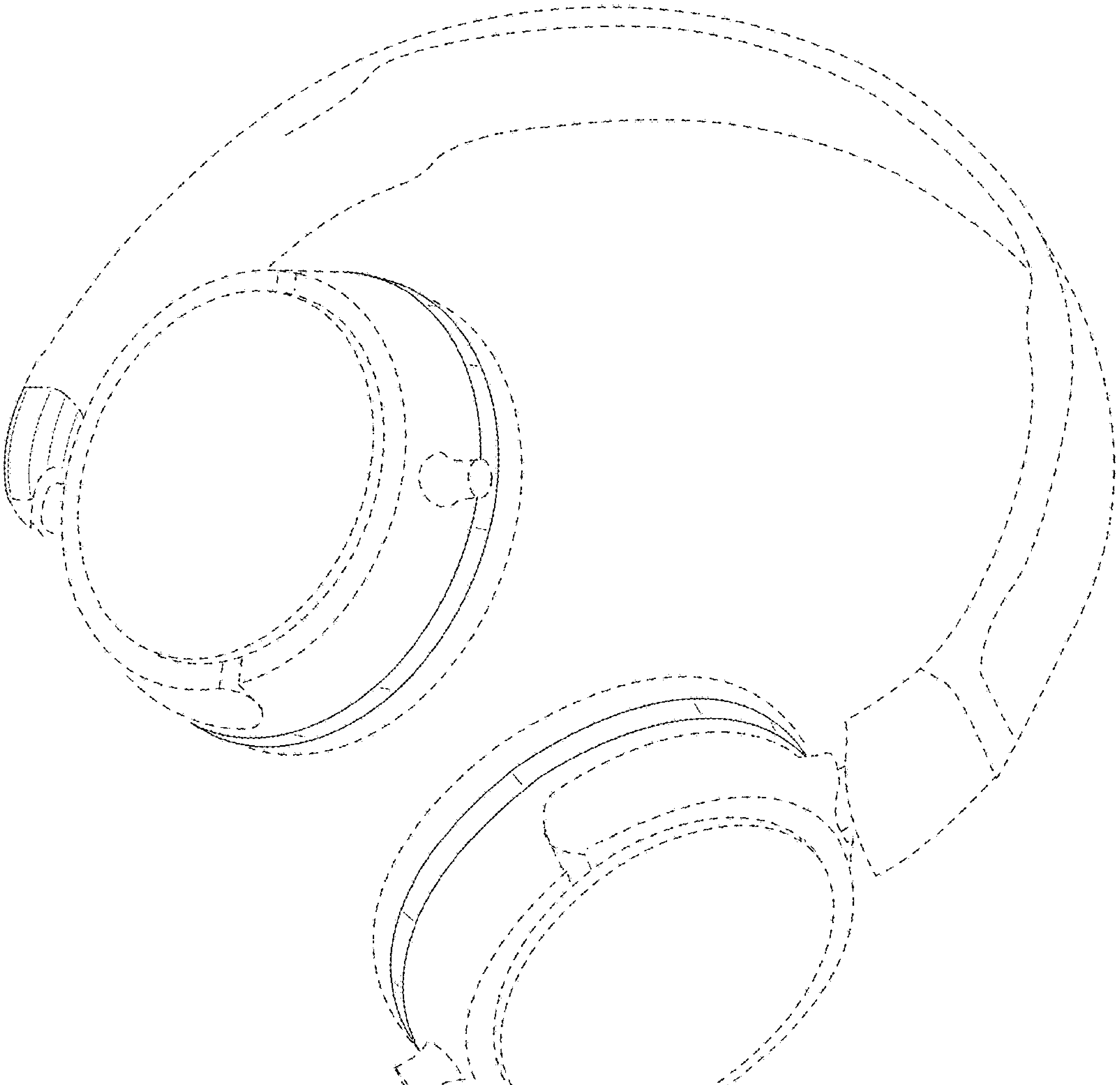


FIG.9



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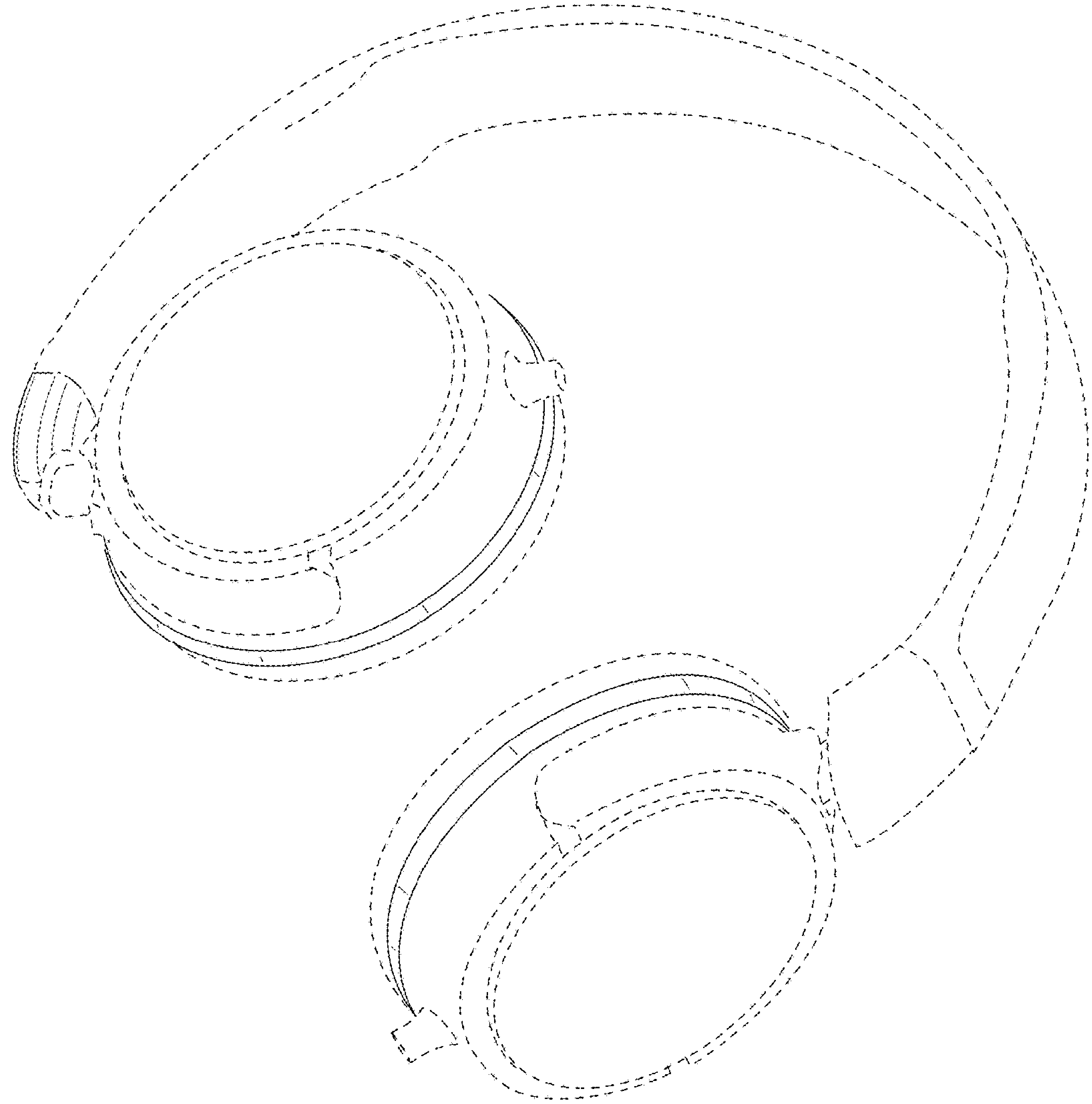

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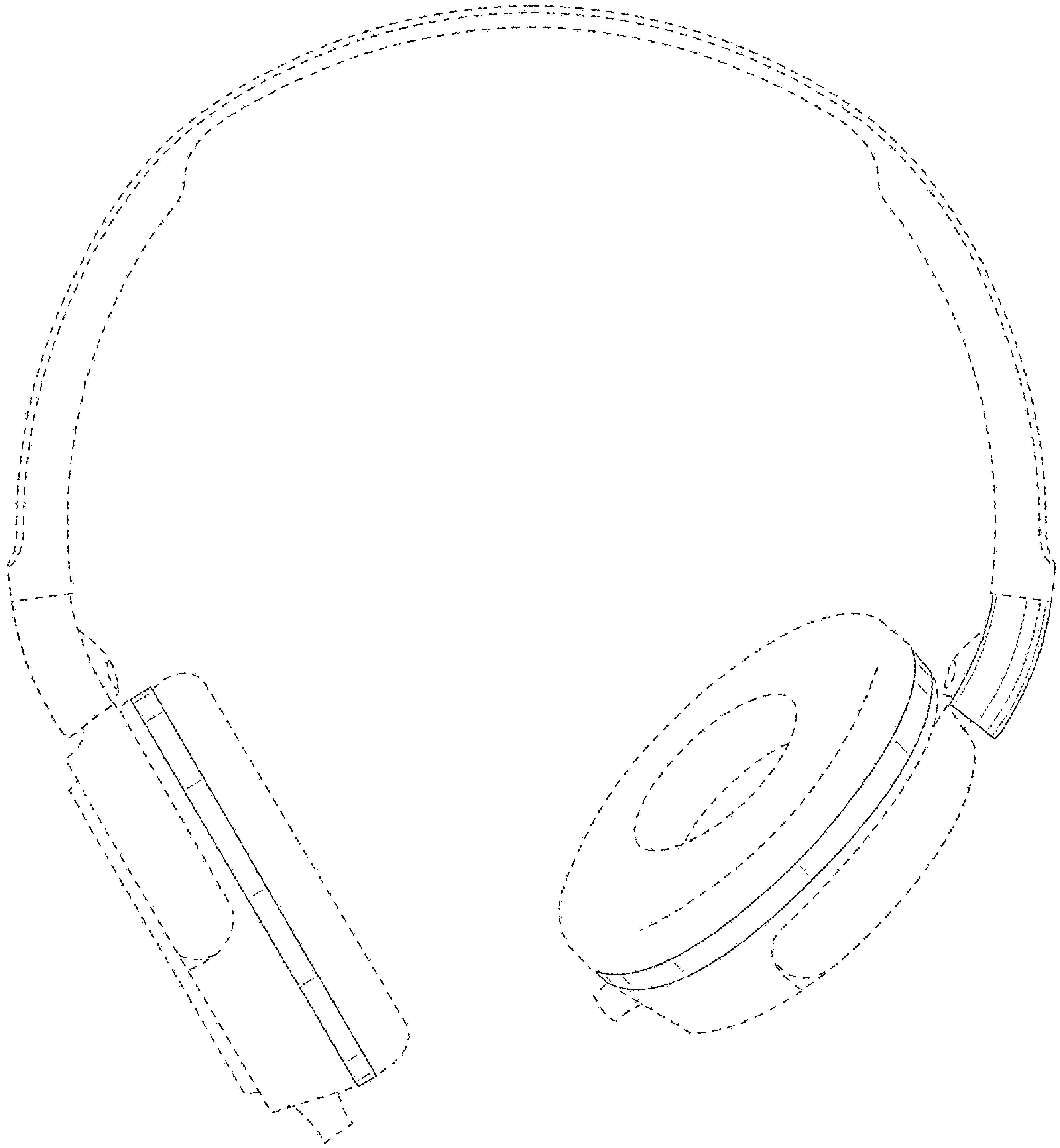
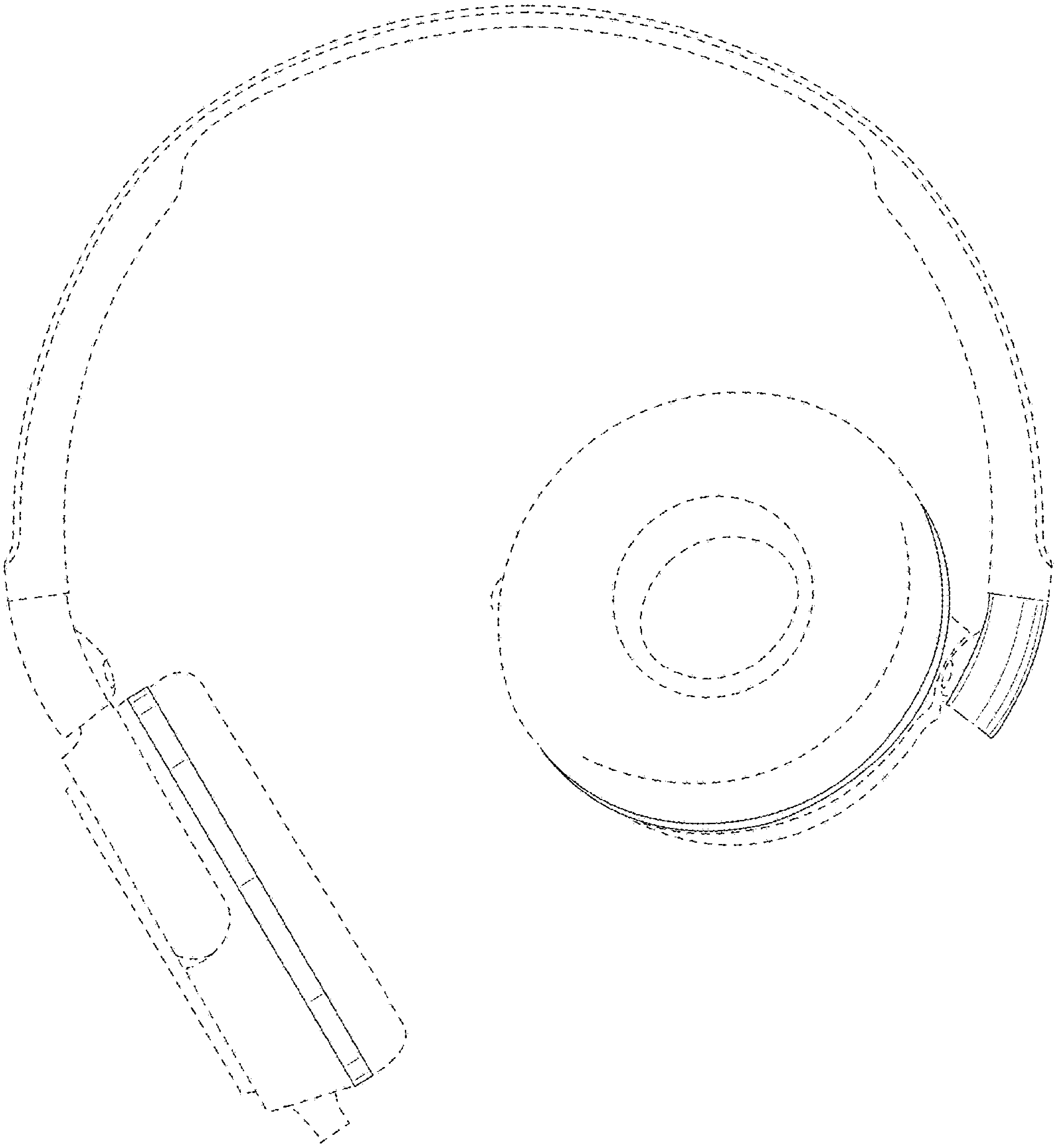


FIG.12

FIG.13



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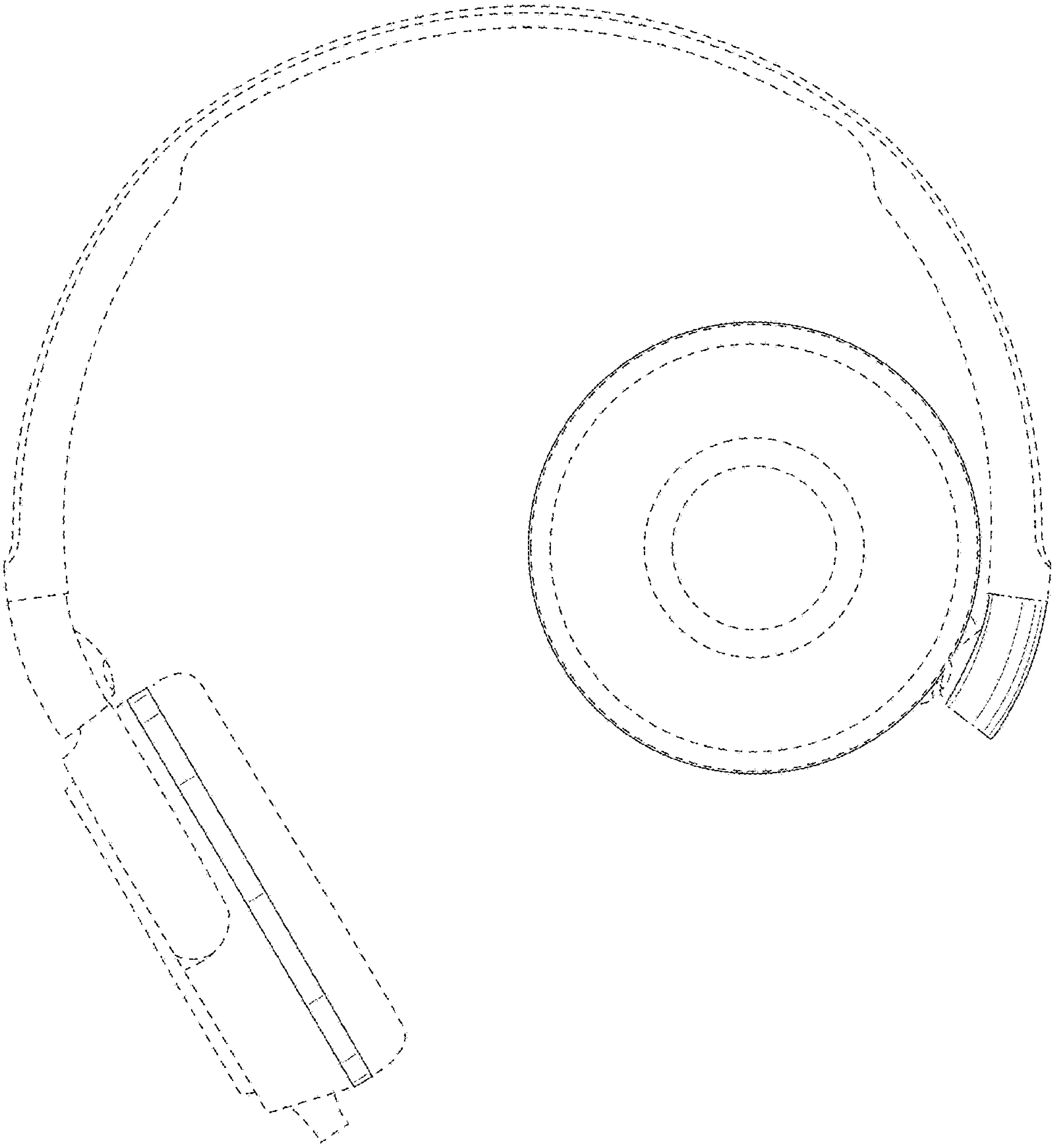

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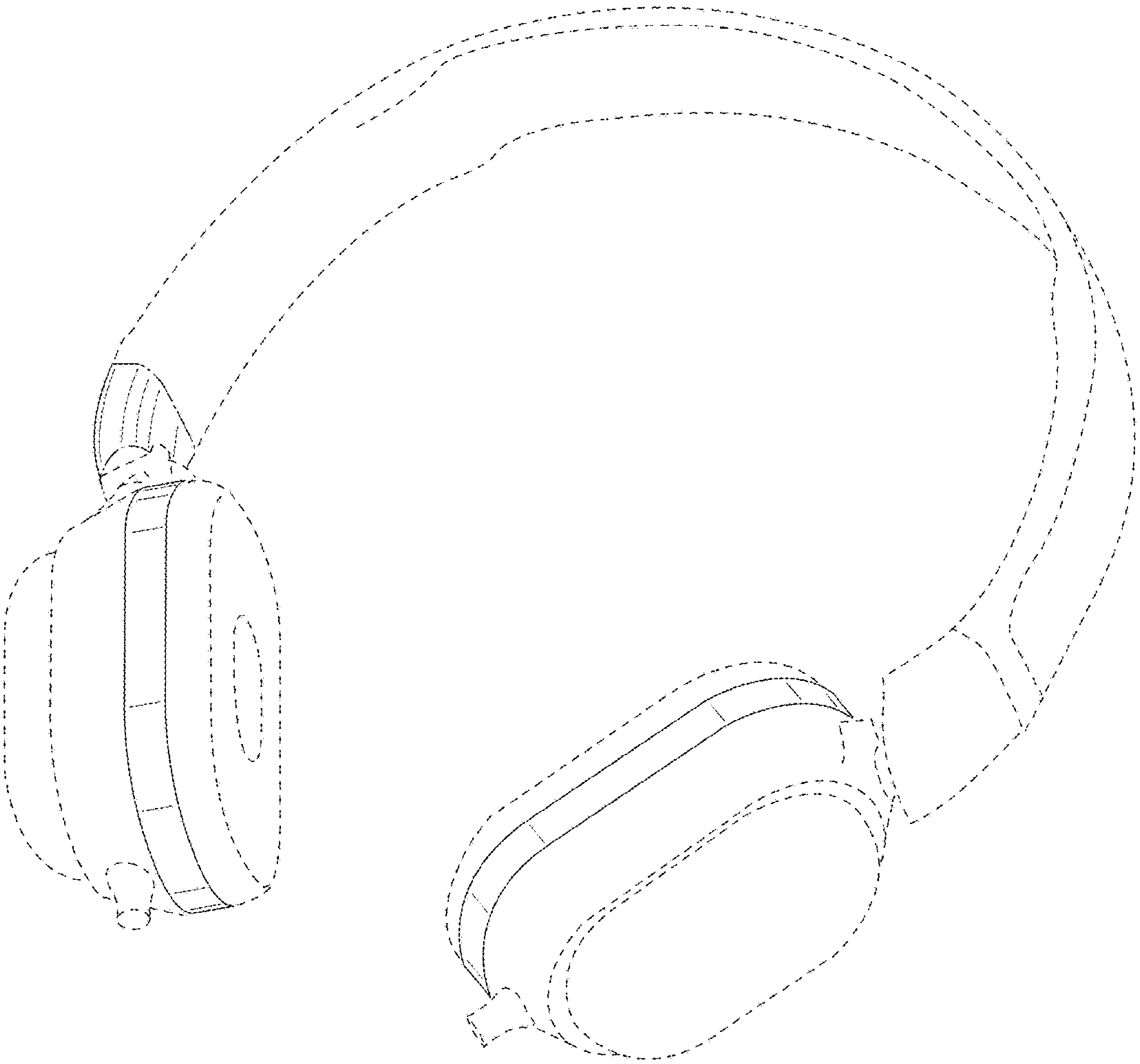

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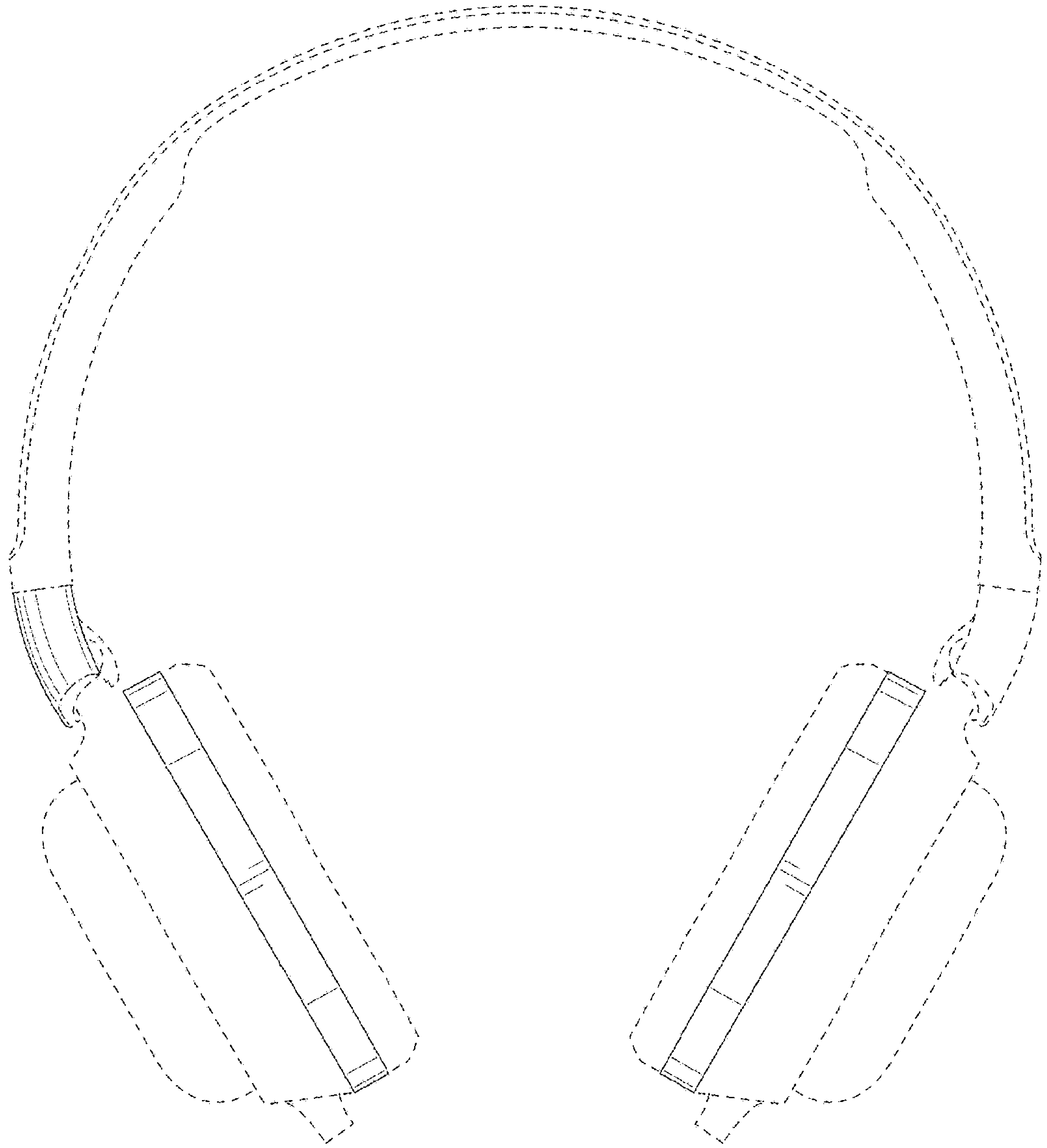


FIG.17

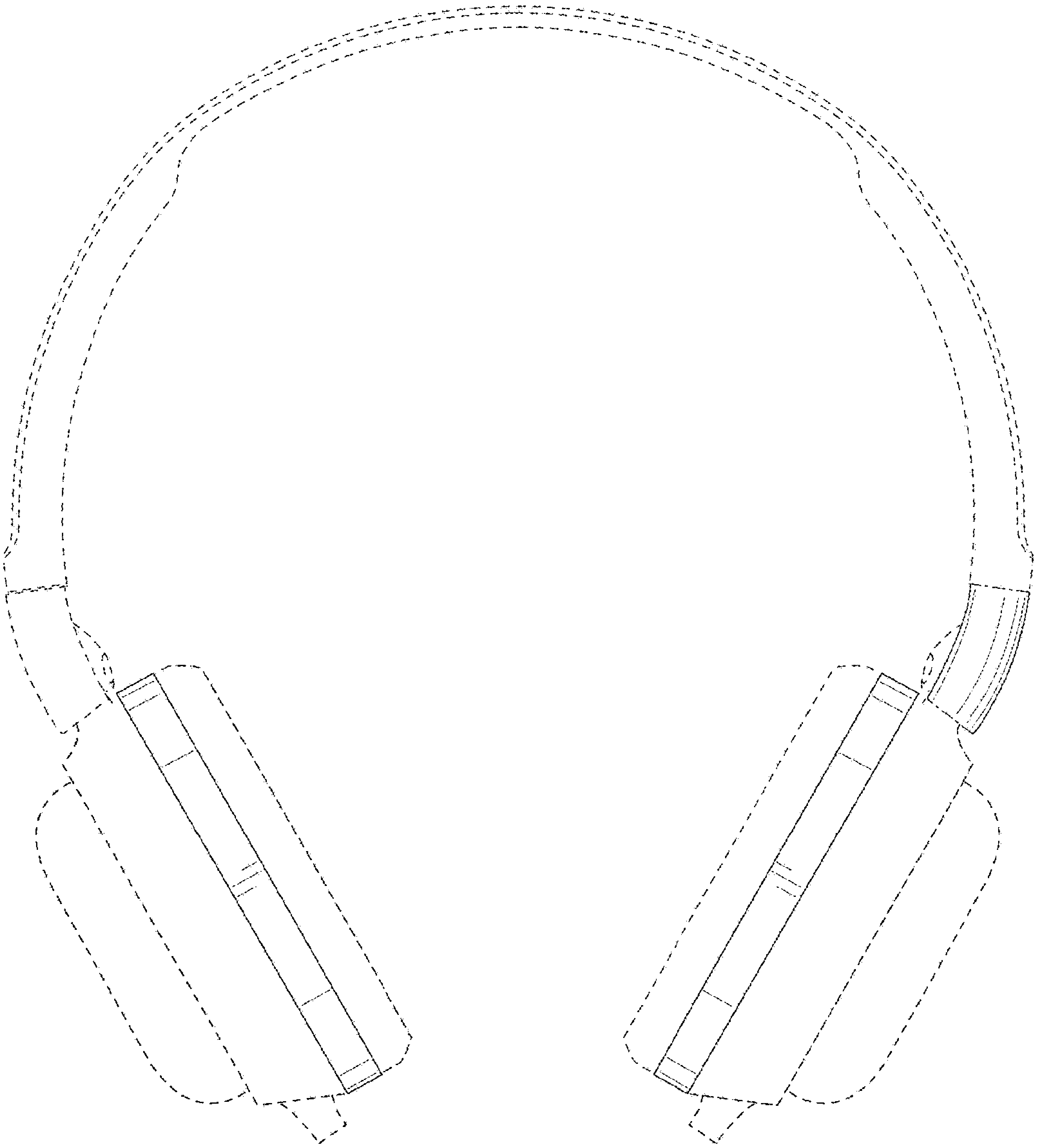
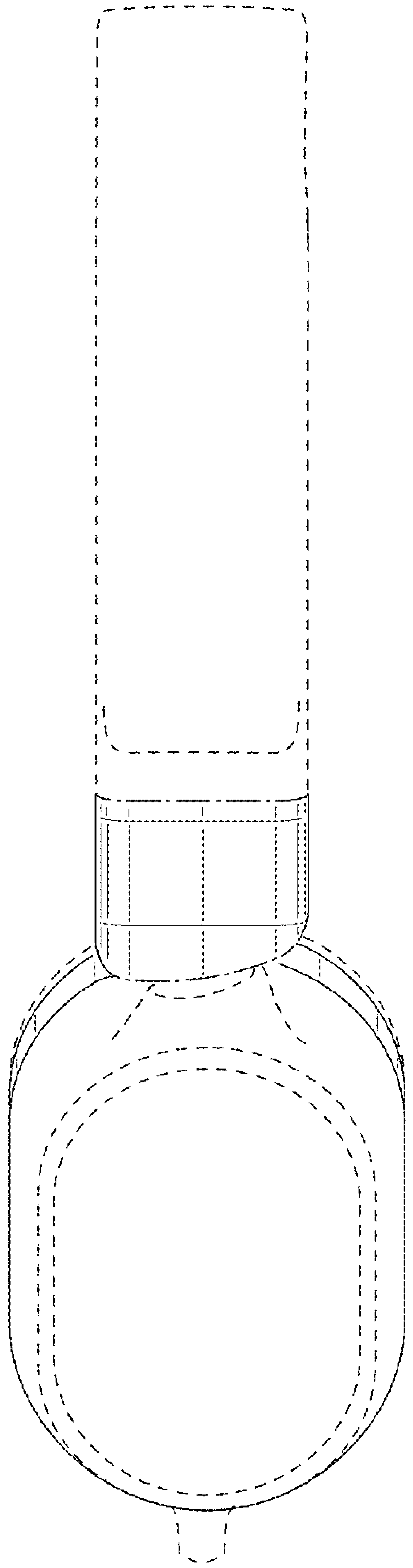


FIG.18



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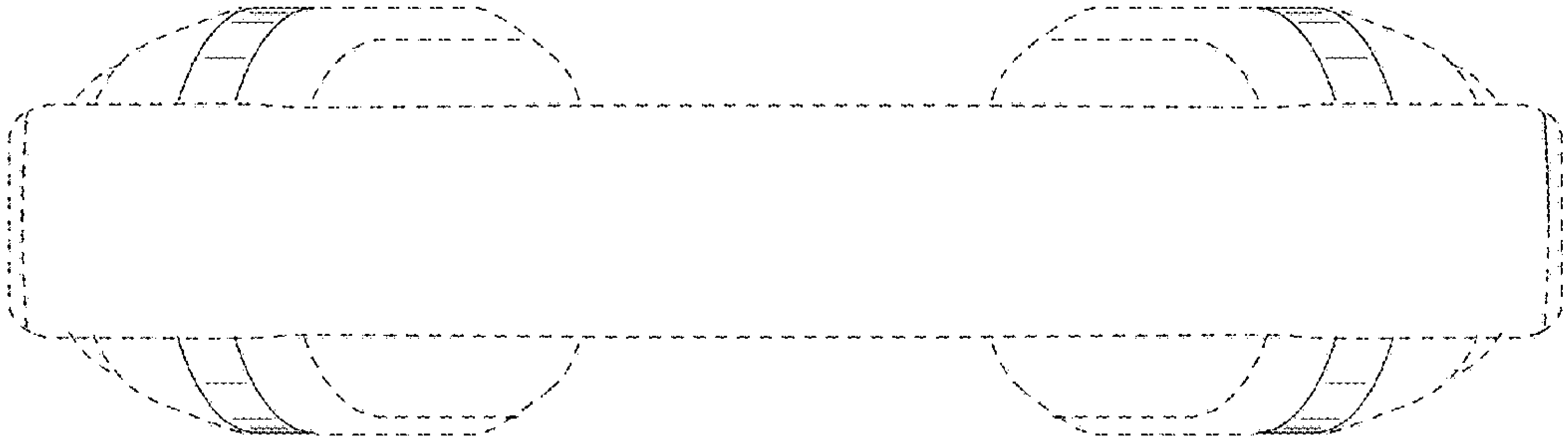


FIG.20

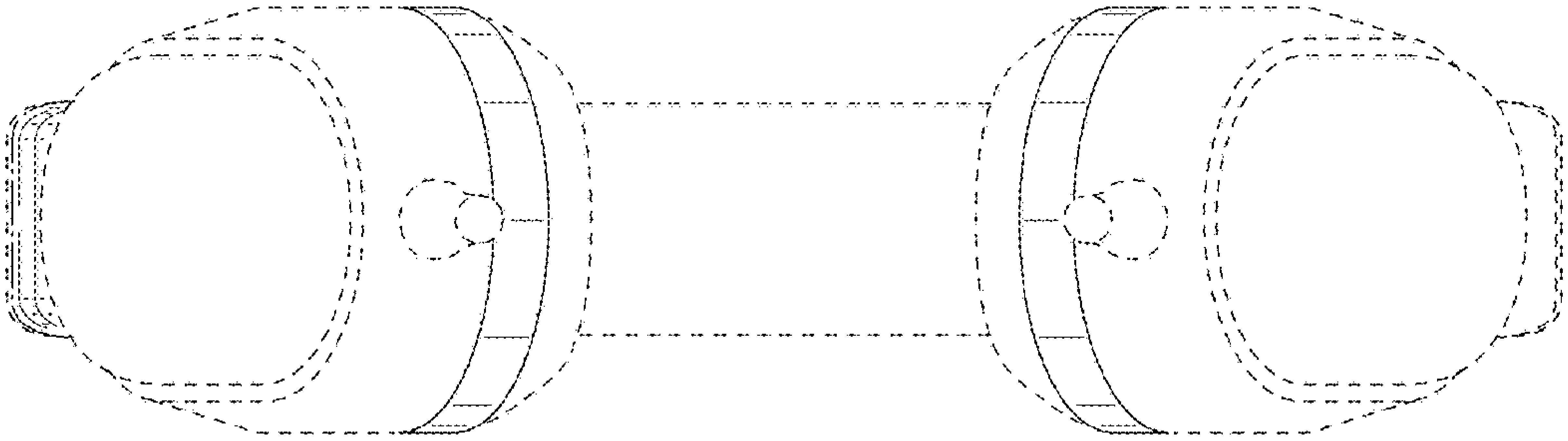


FIG.21

FIG.22

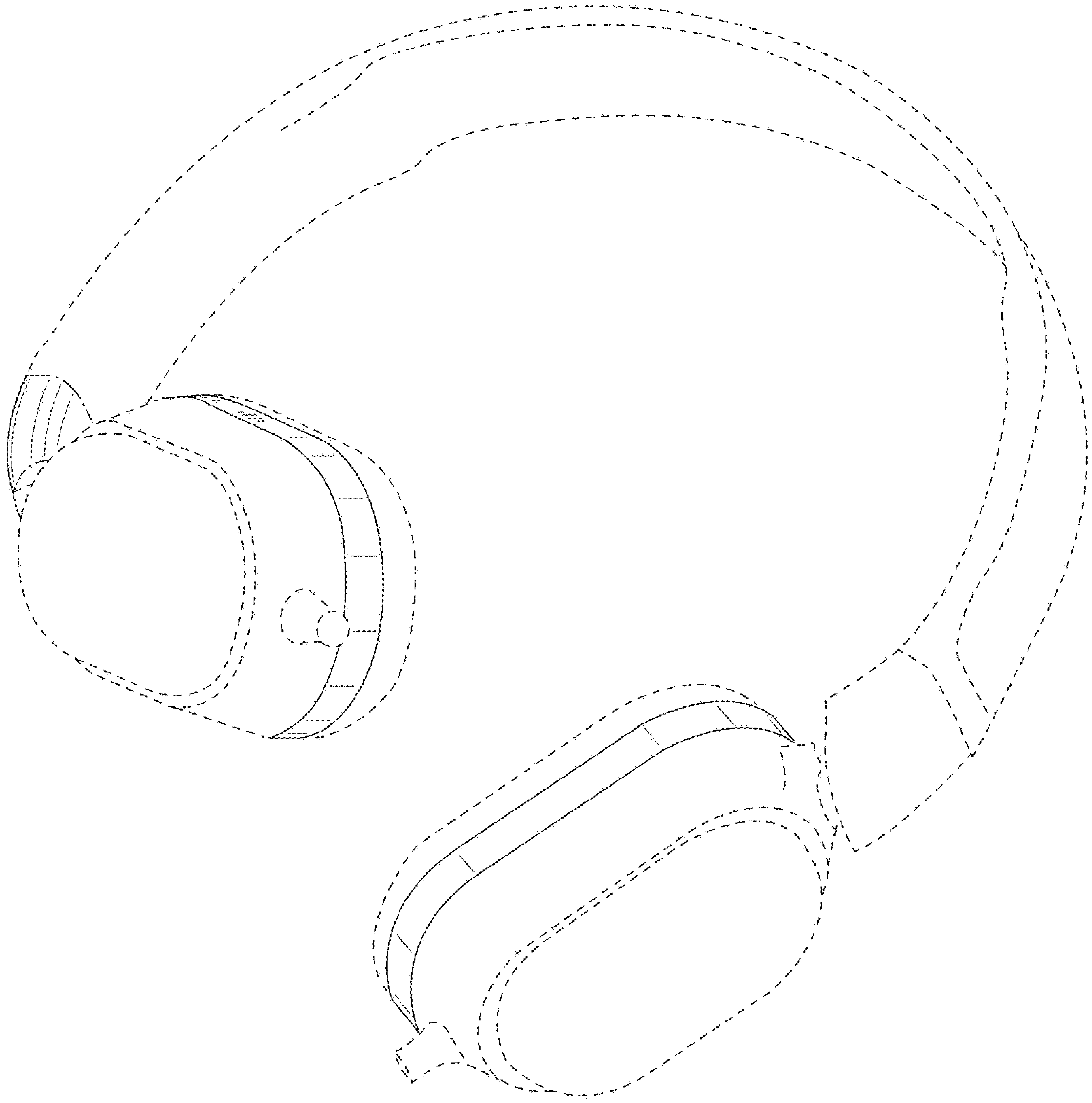


FIG.23

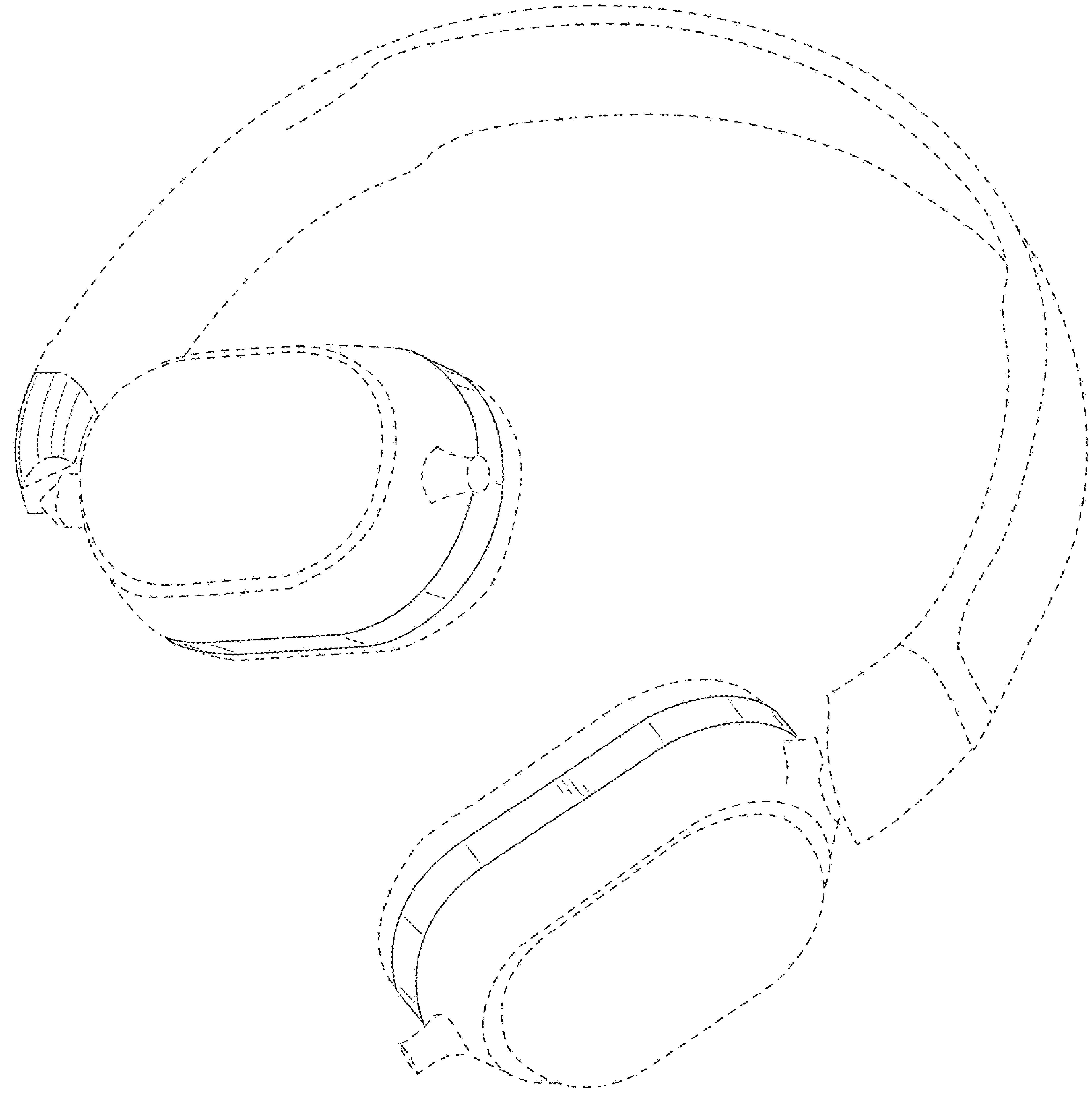


FIG.24

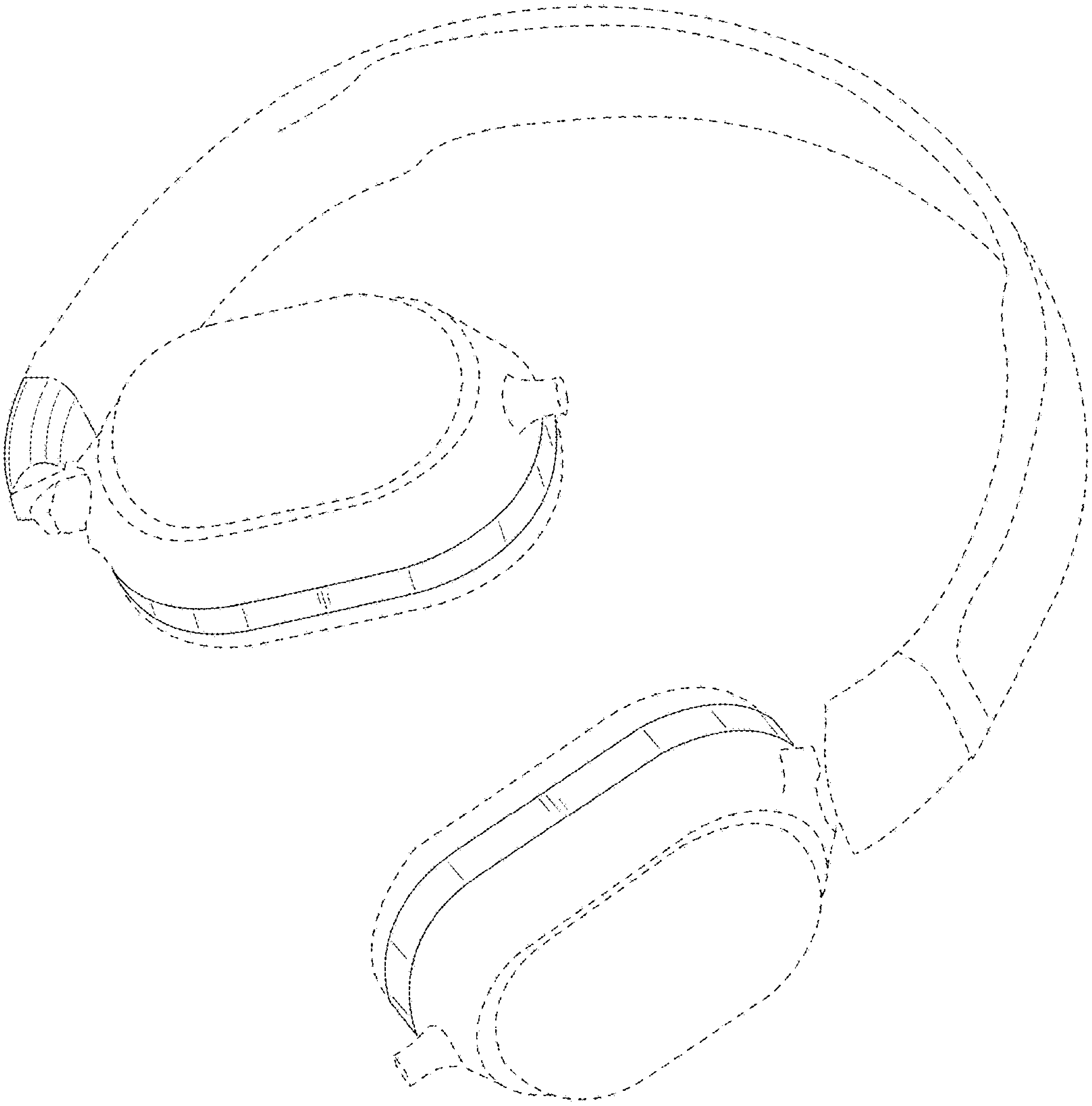


FIG.25

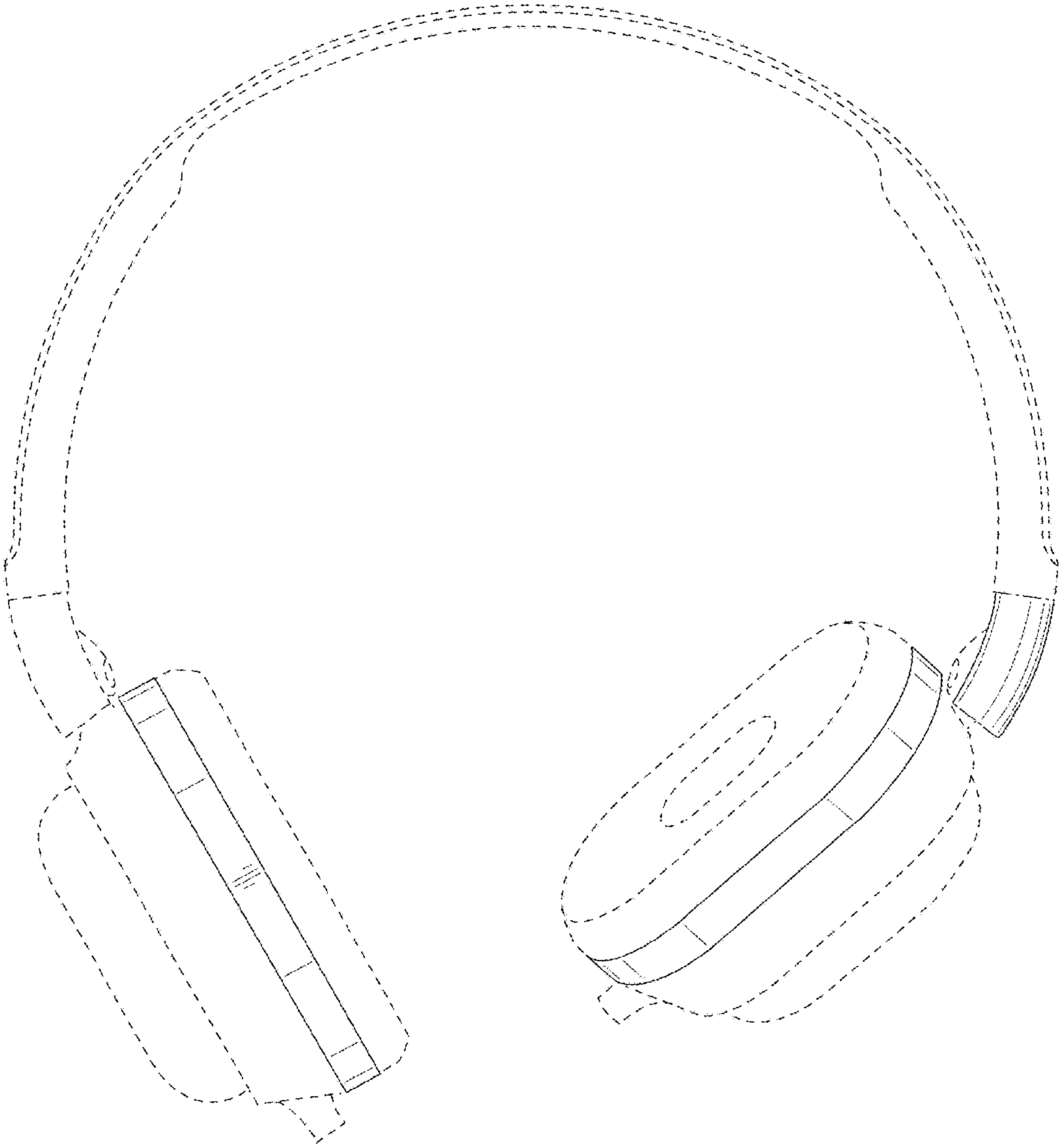
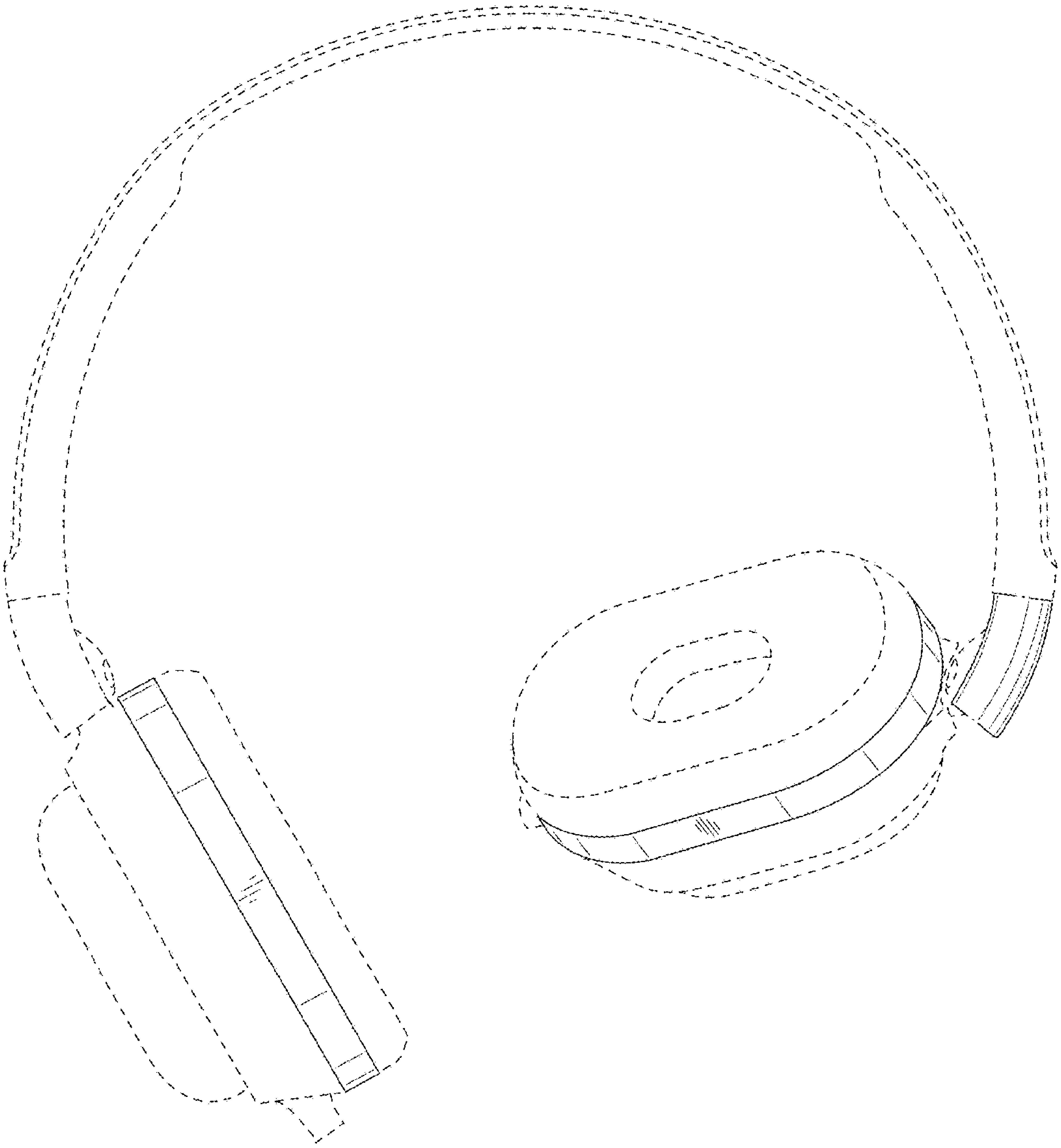


FIG.26



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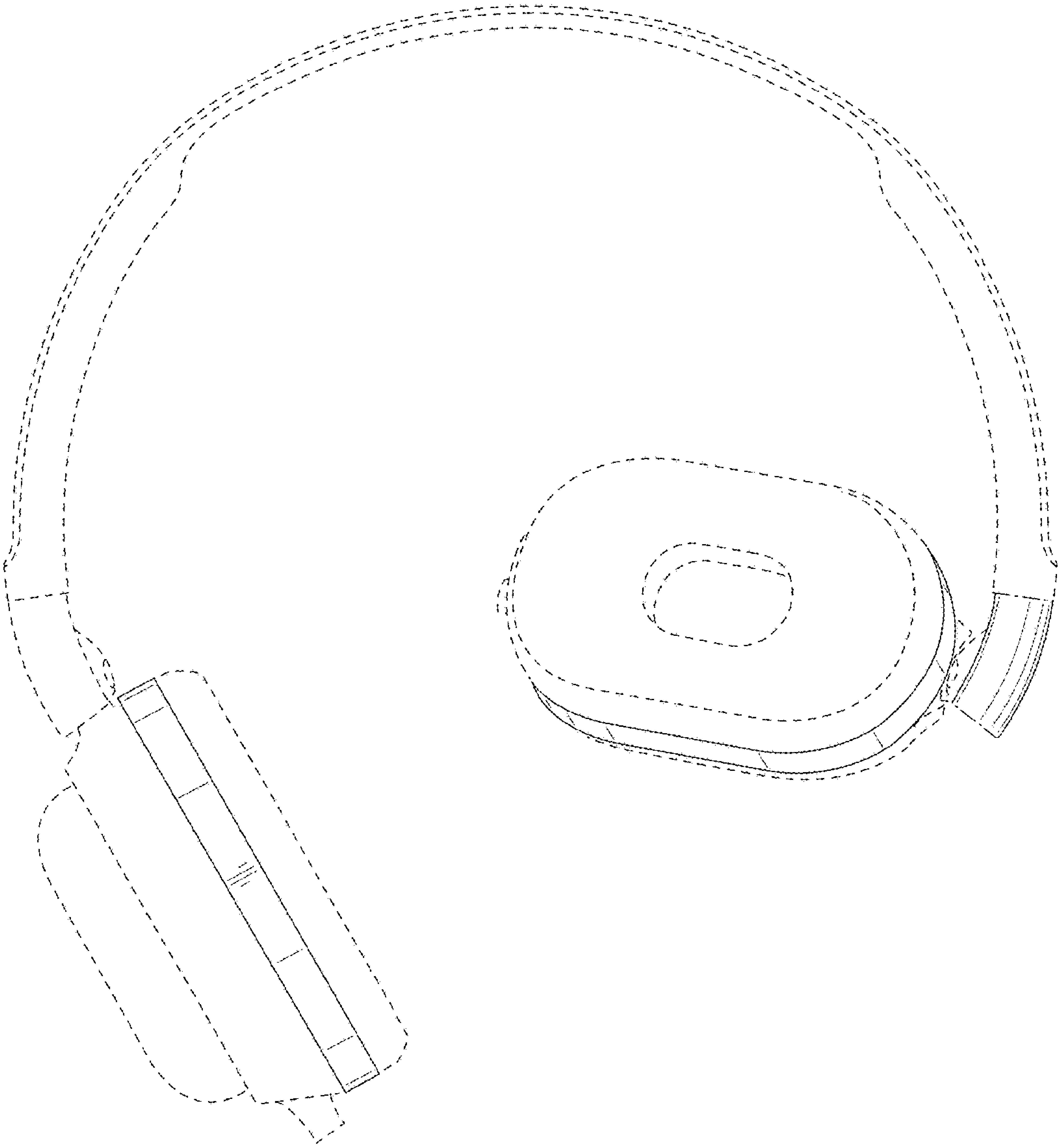

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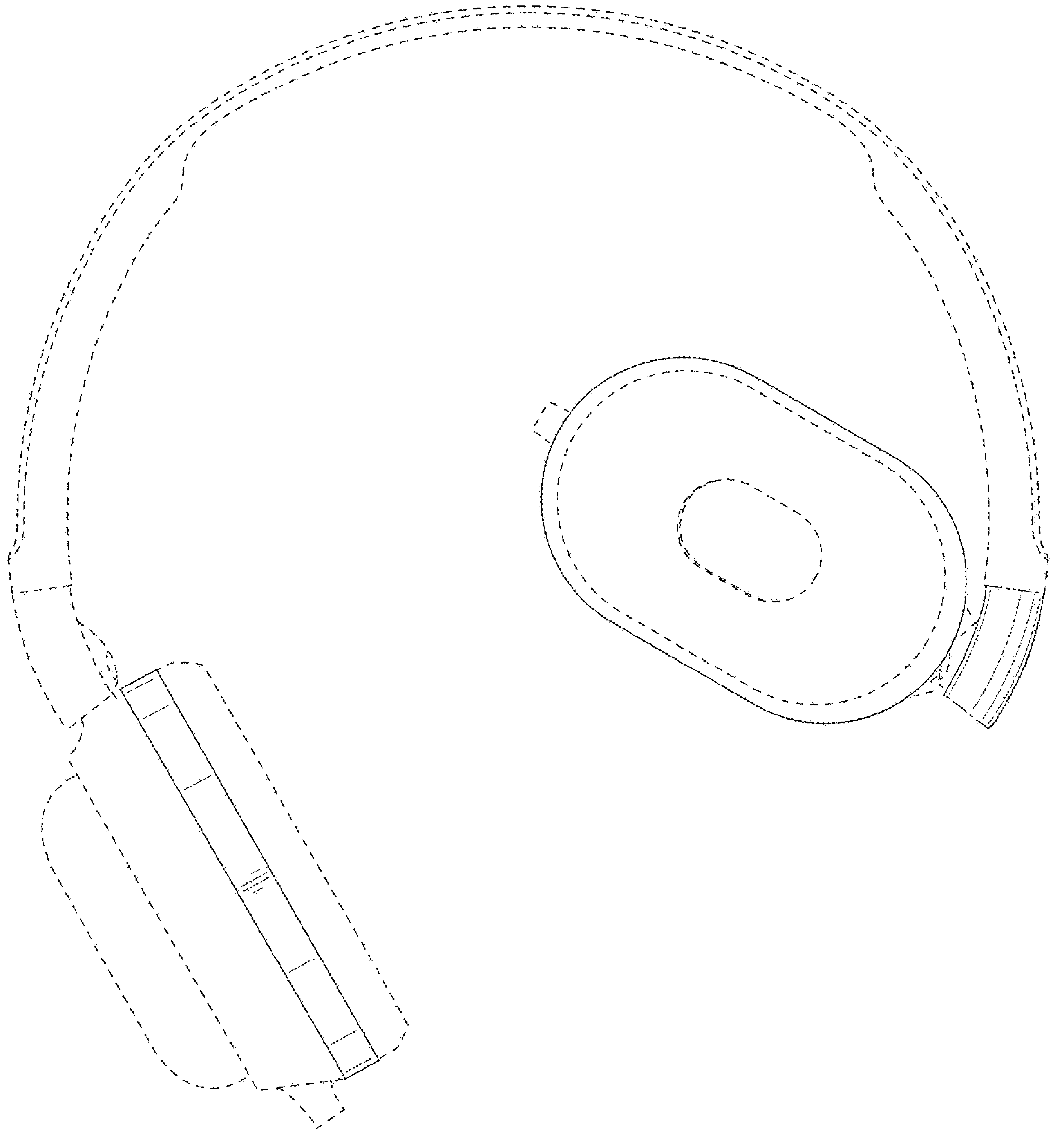

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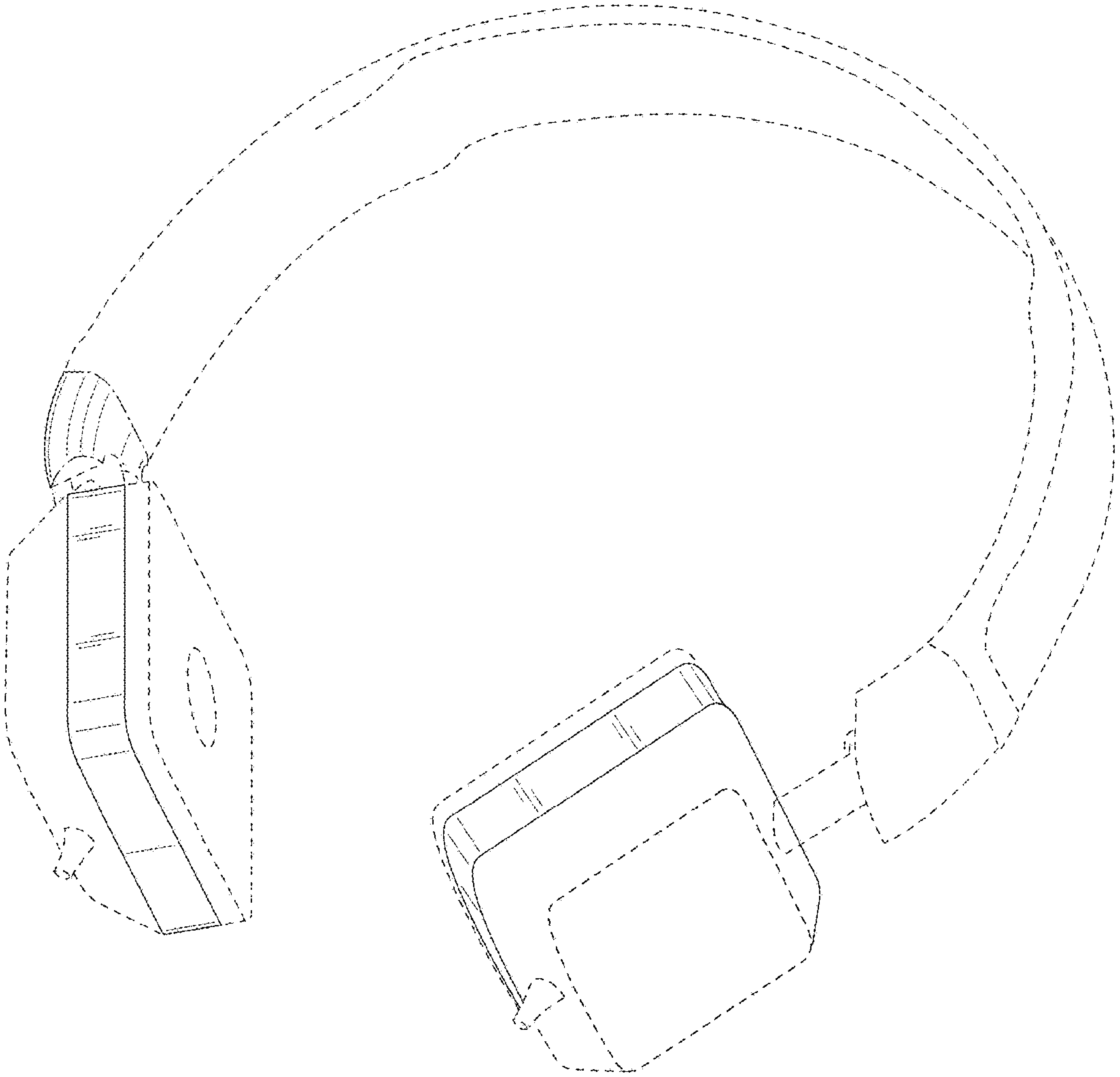

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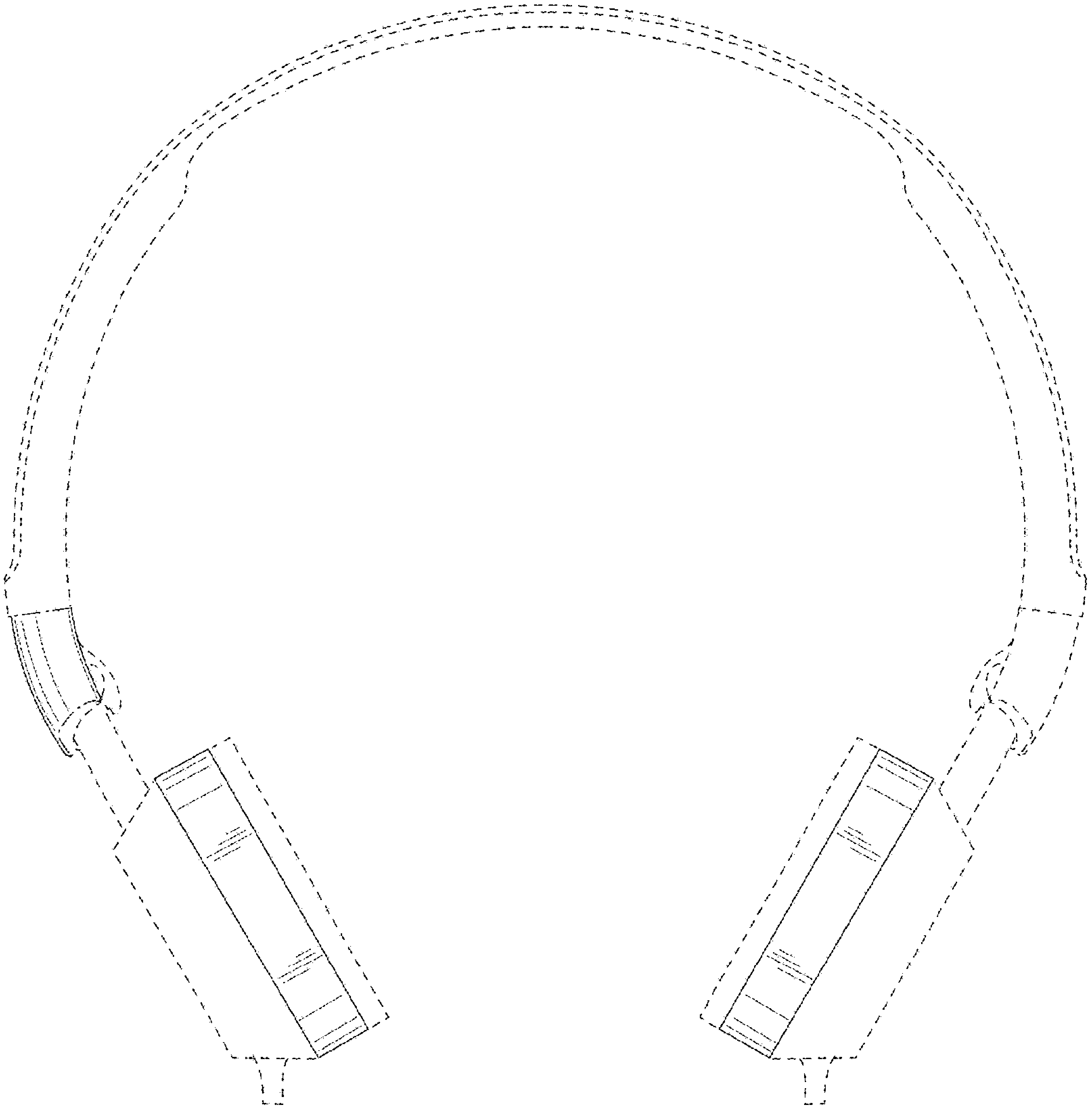

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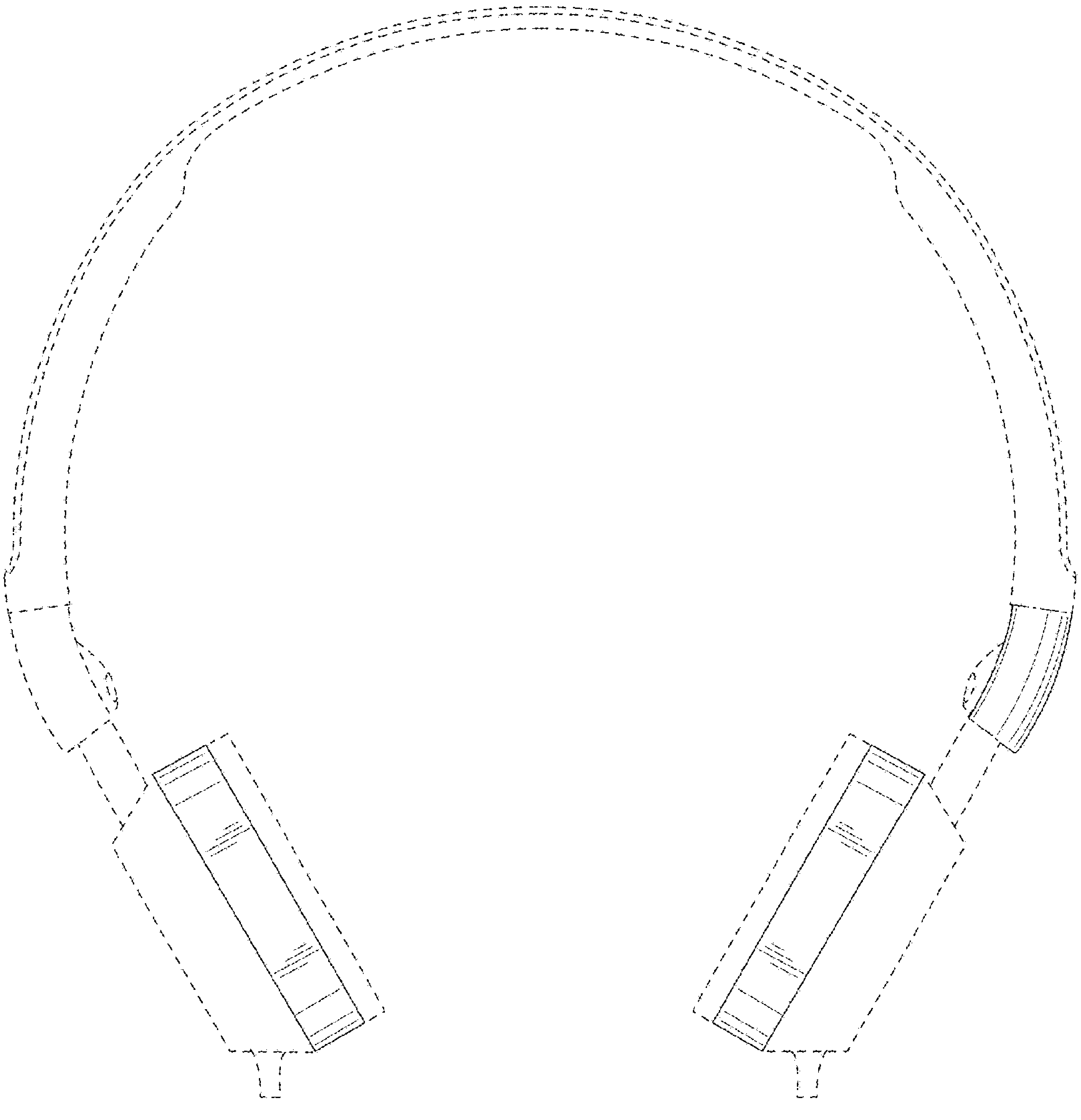

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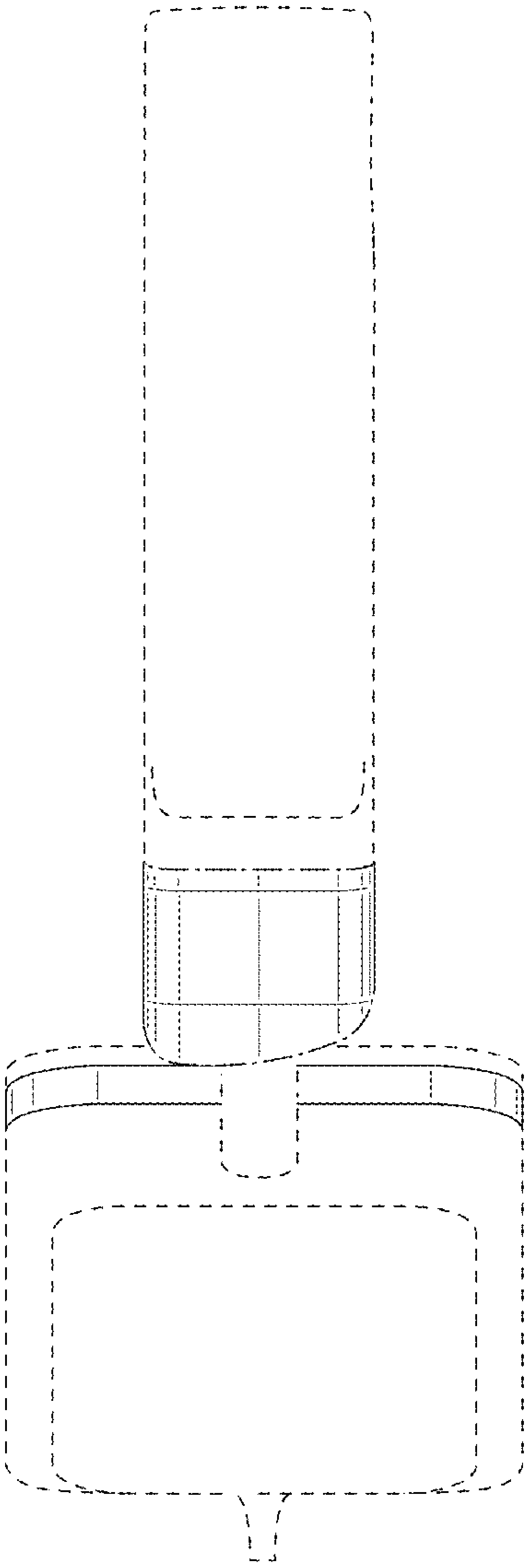

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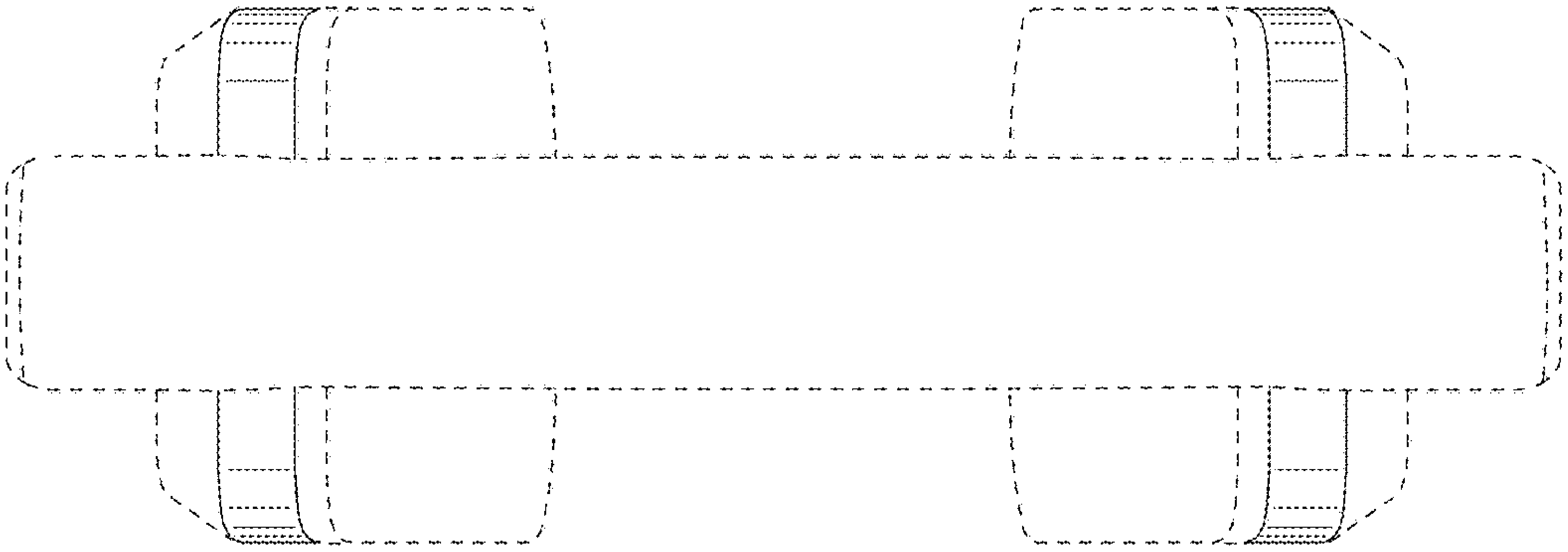

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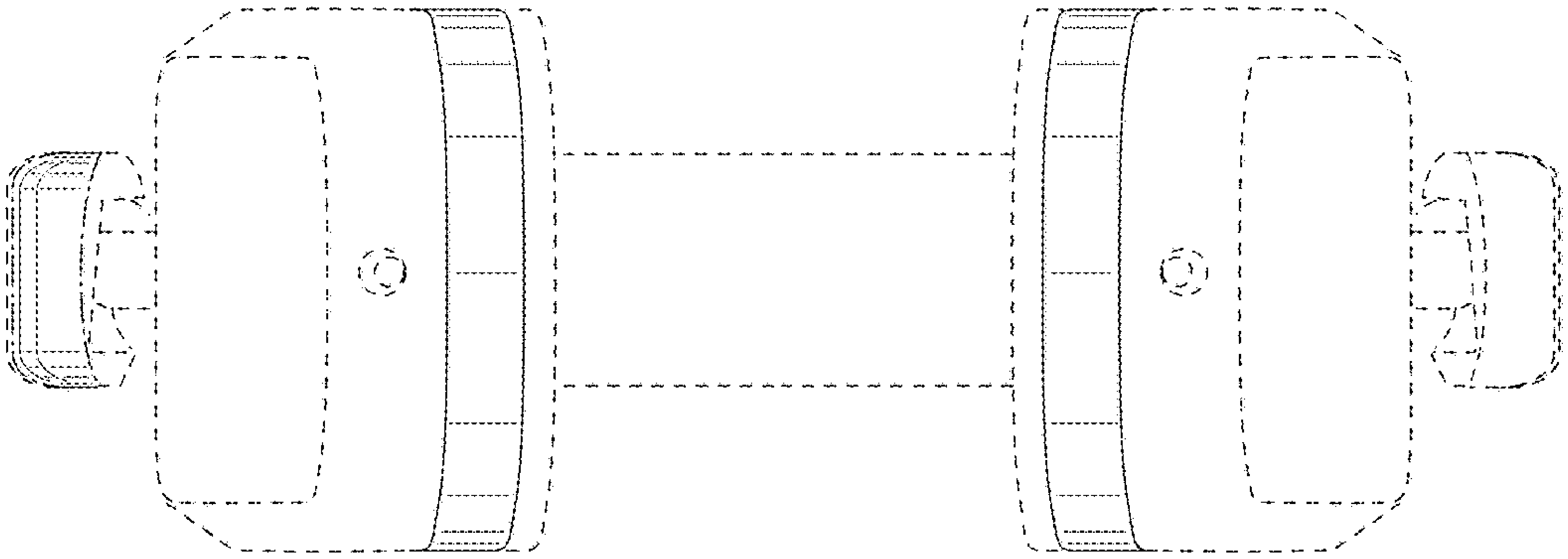

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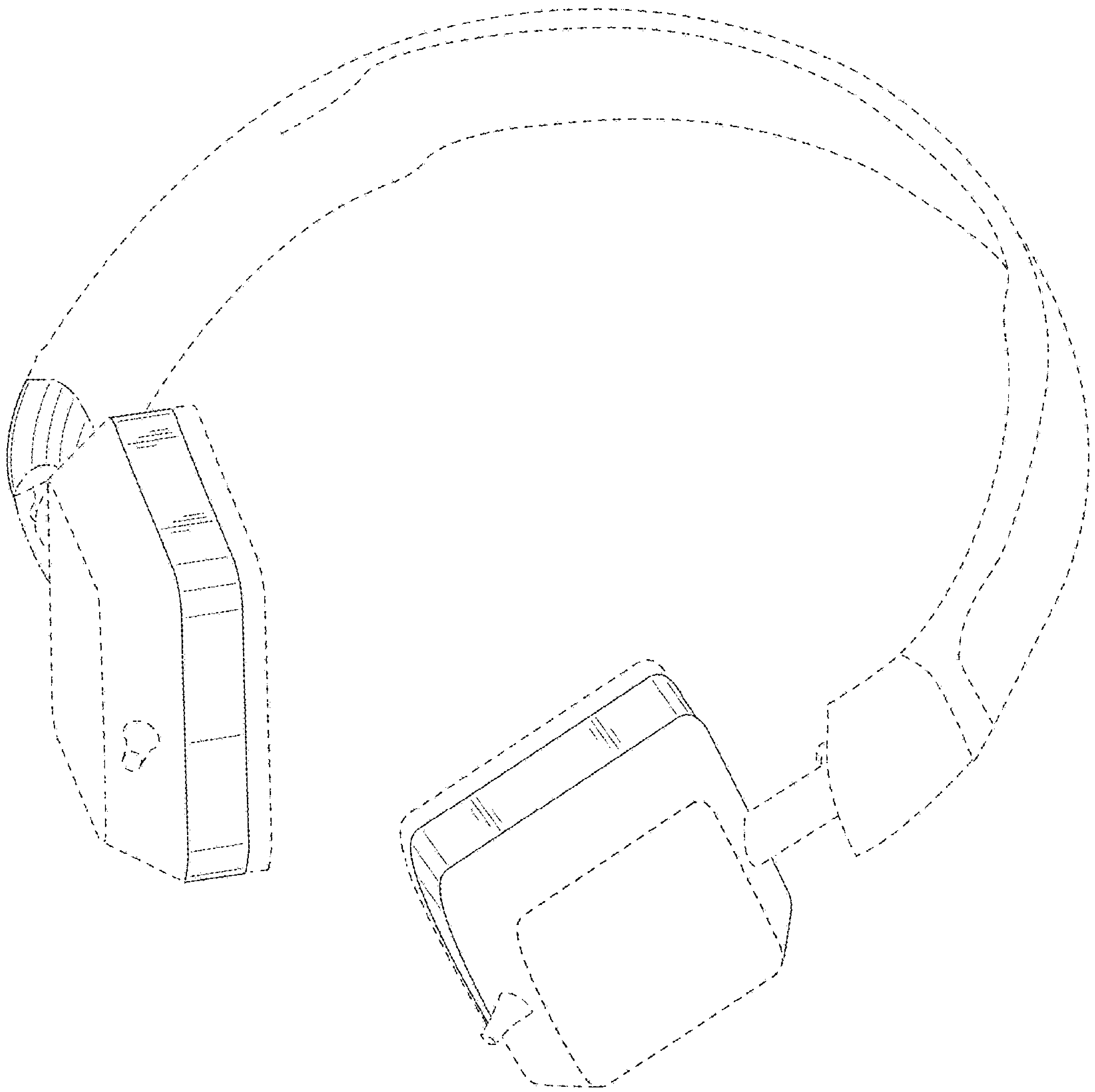

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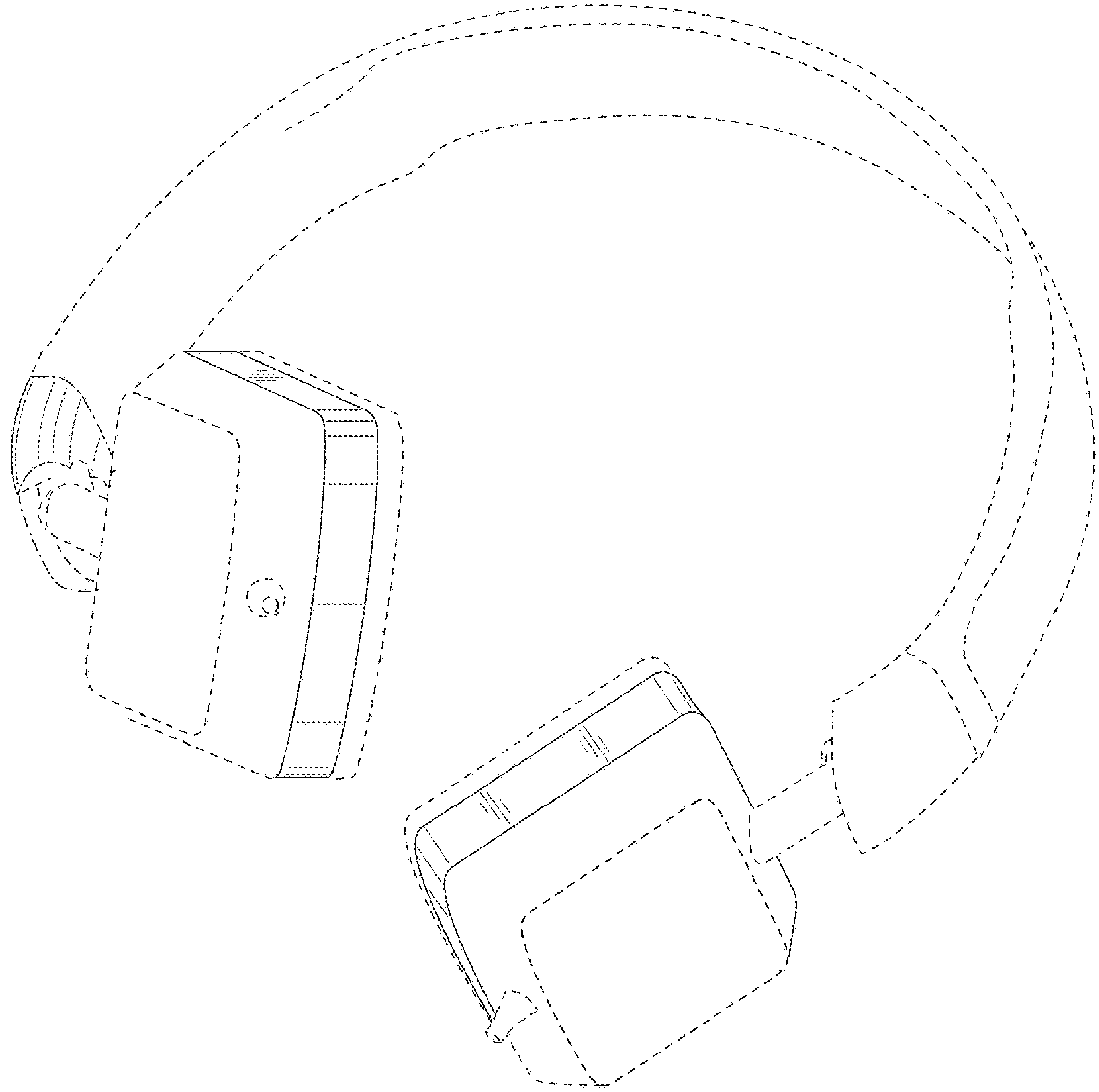

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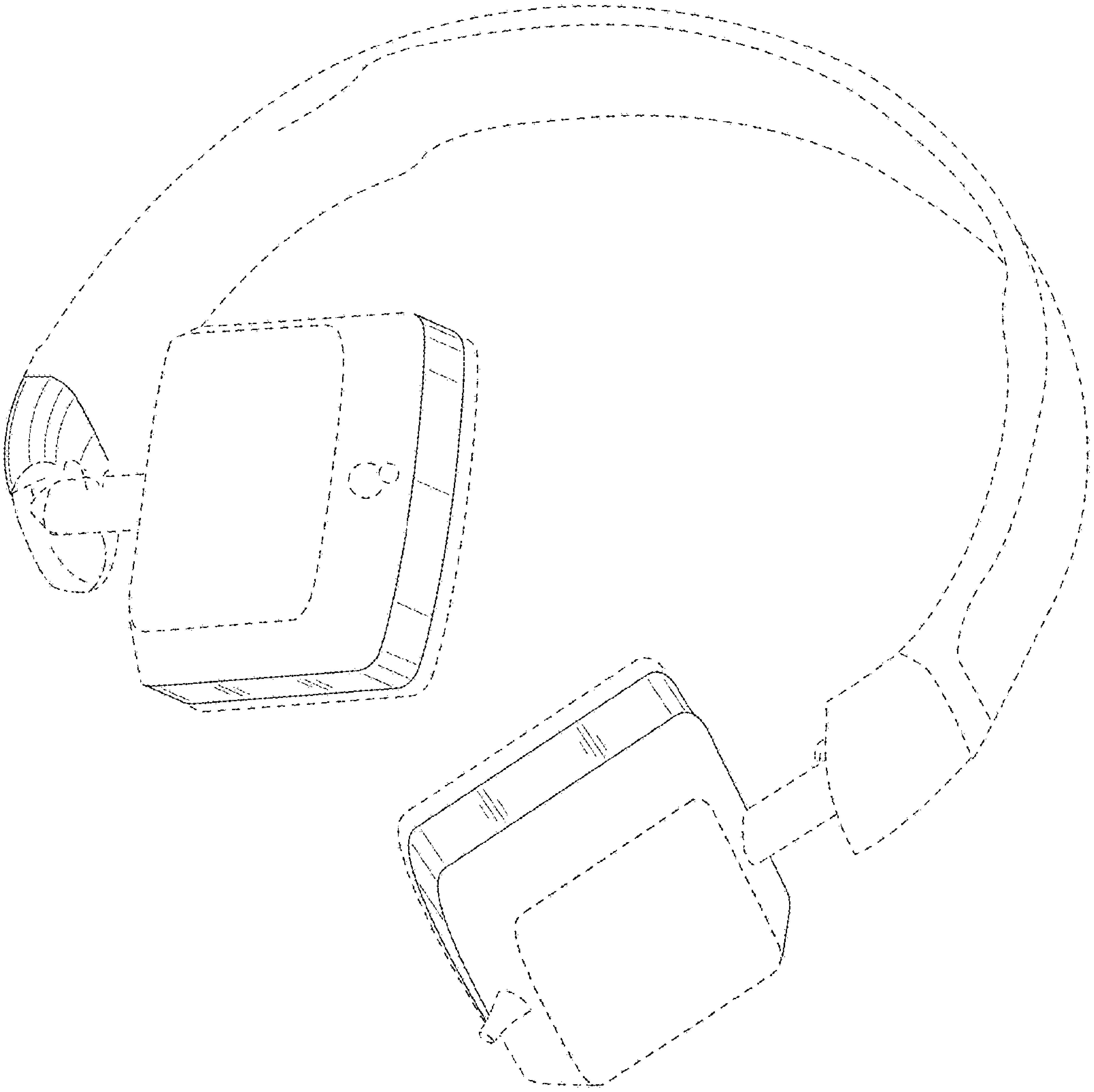

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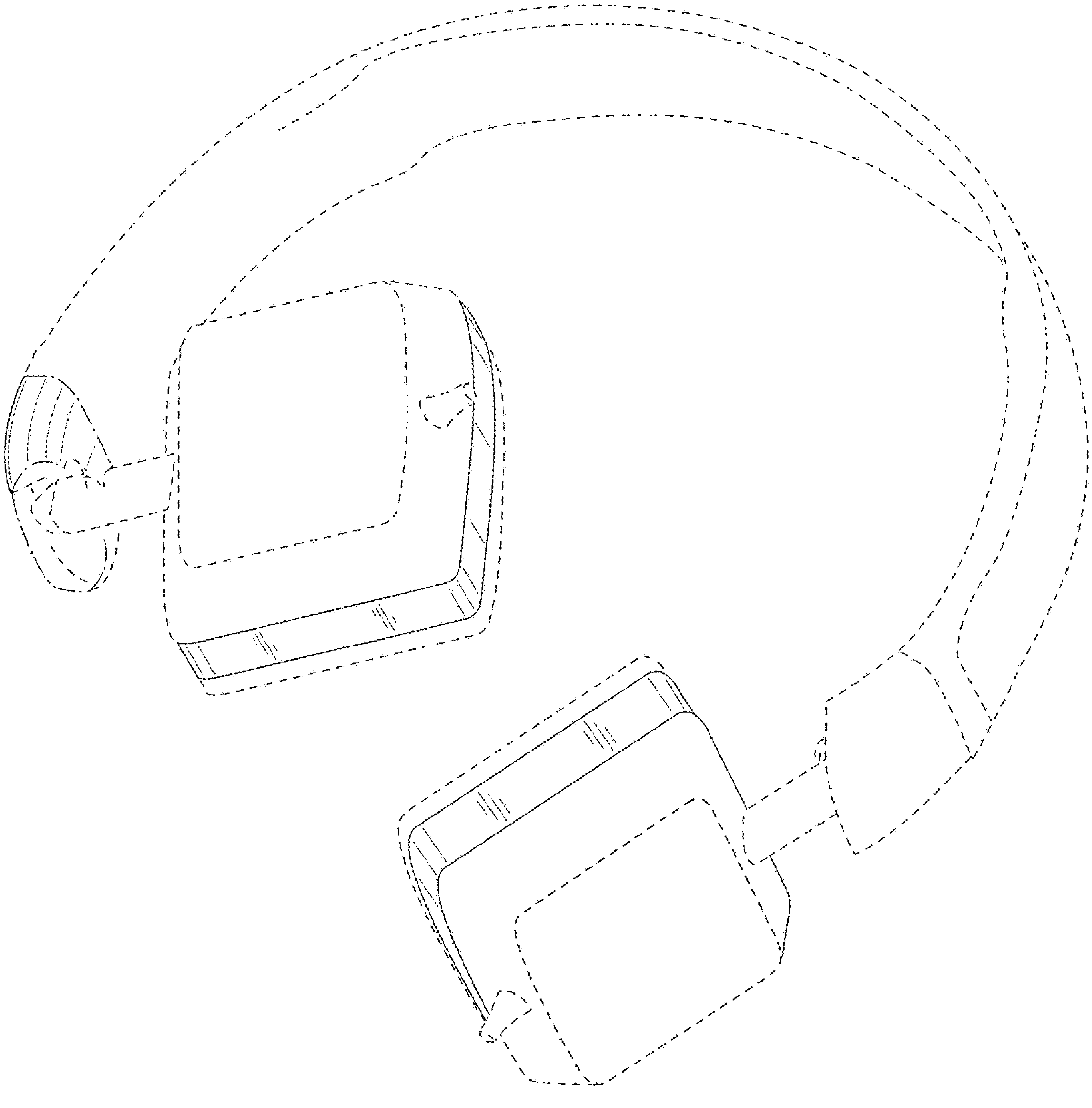

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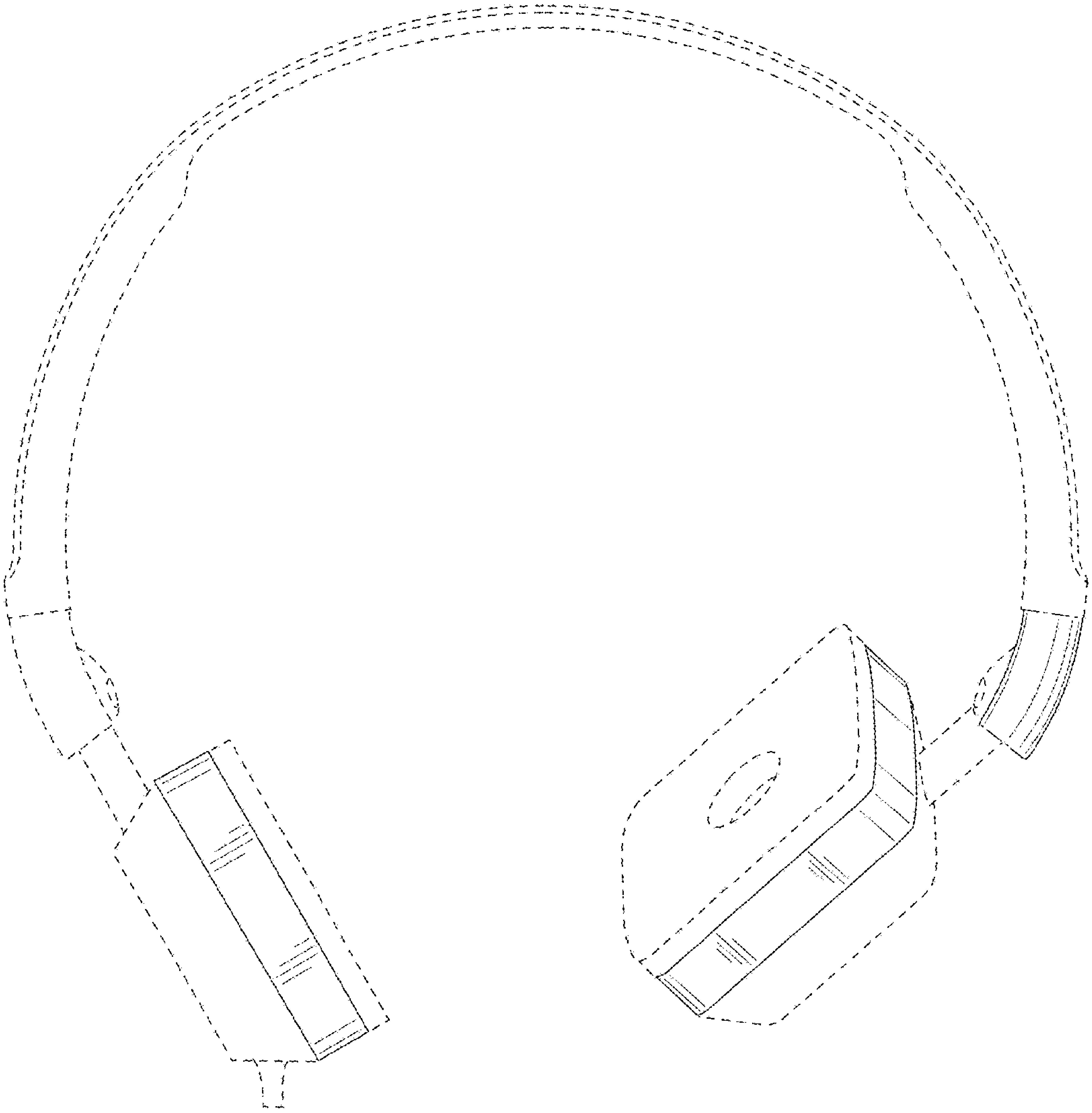

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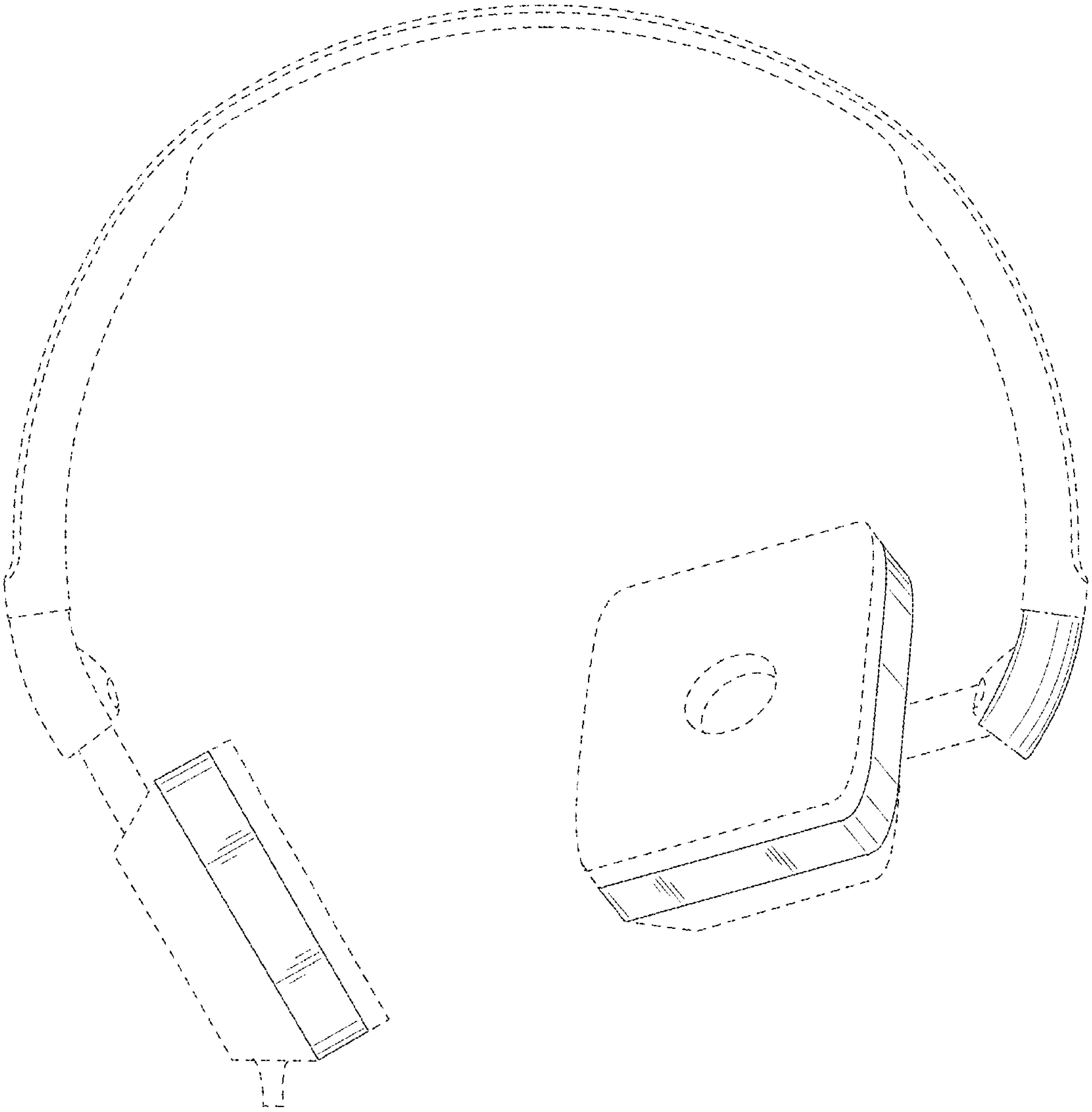

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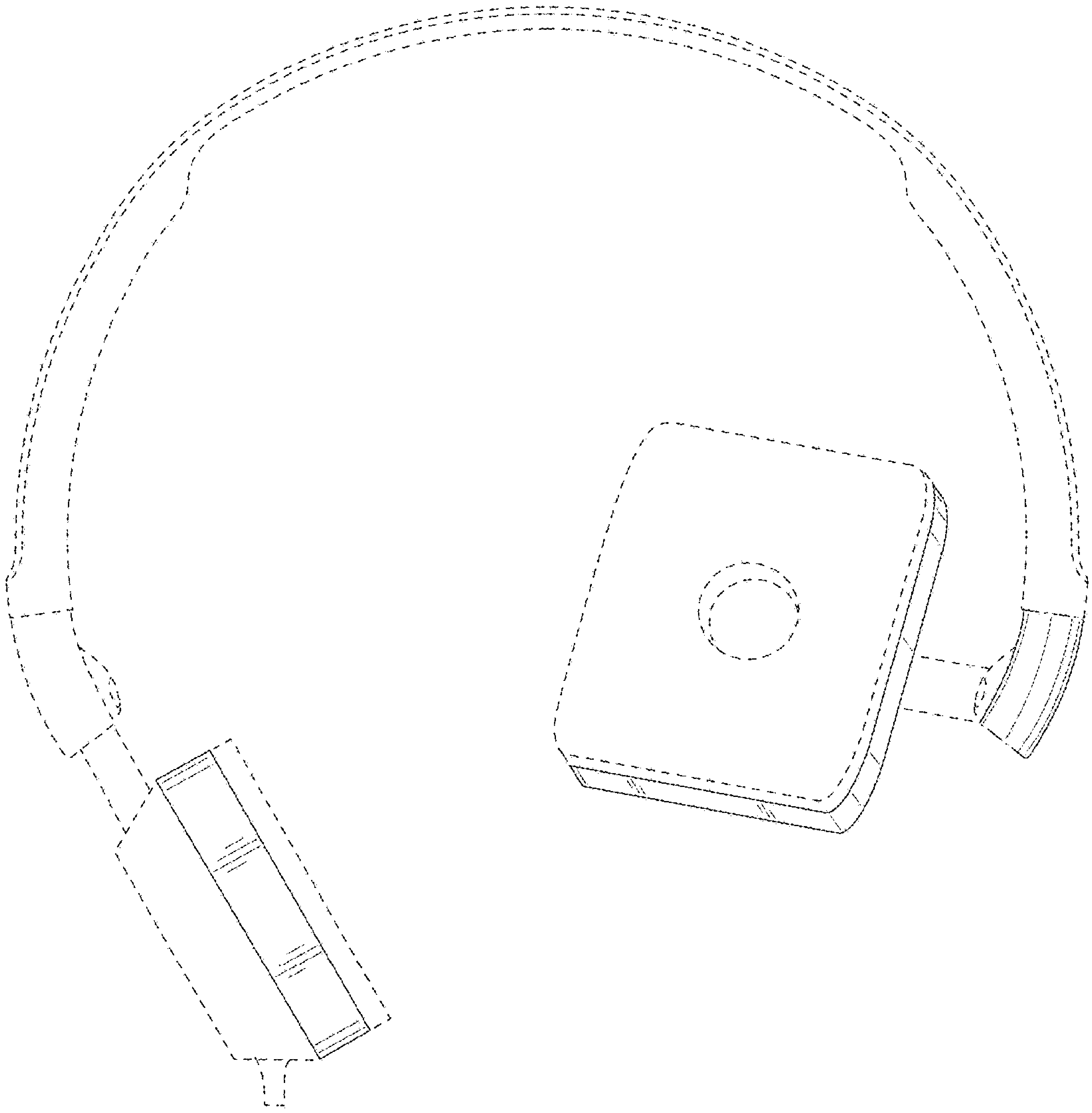

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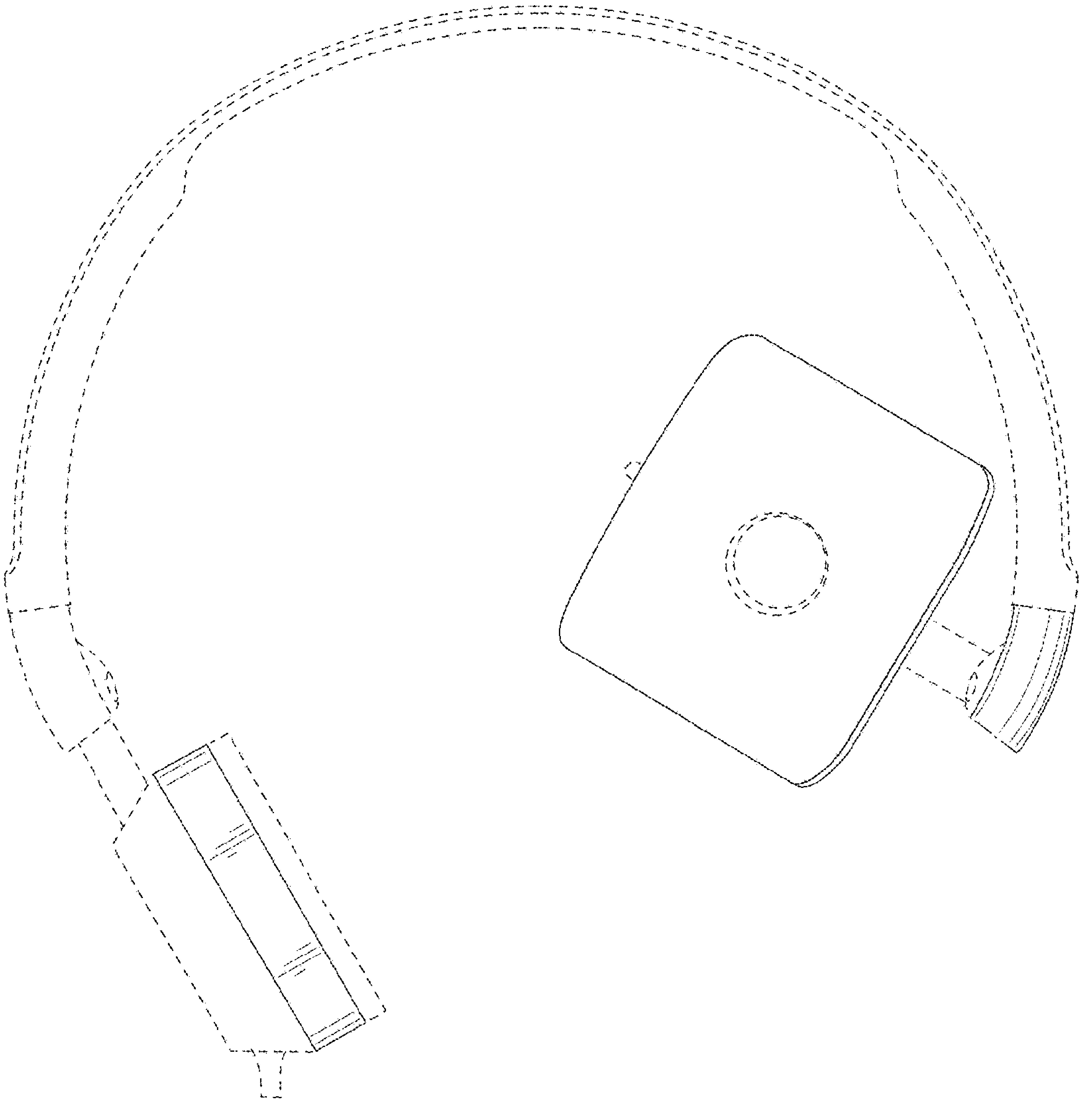

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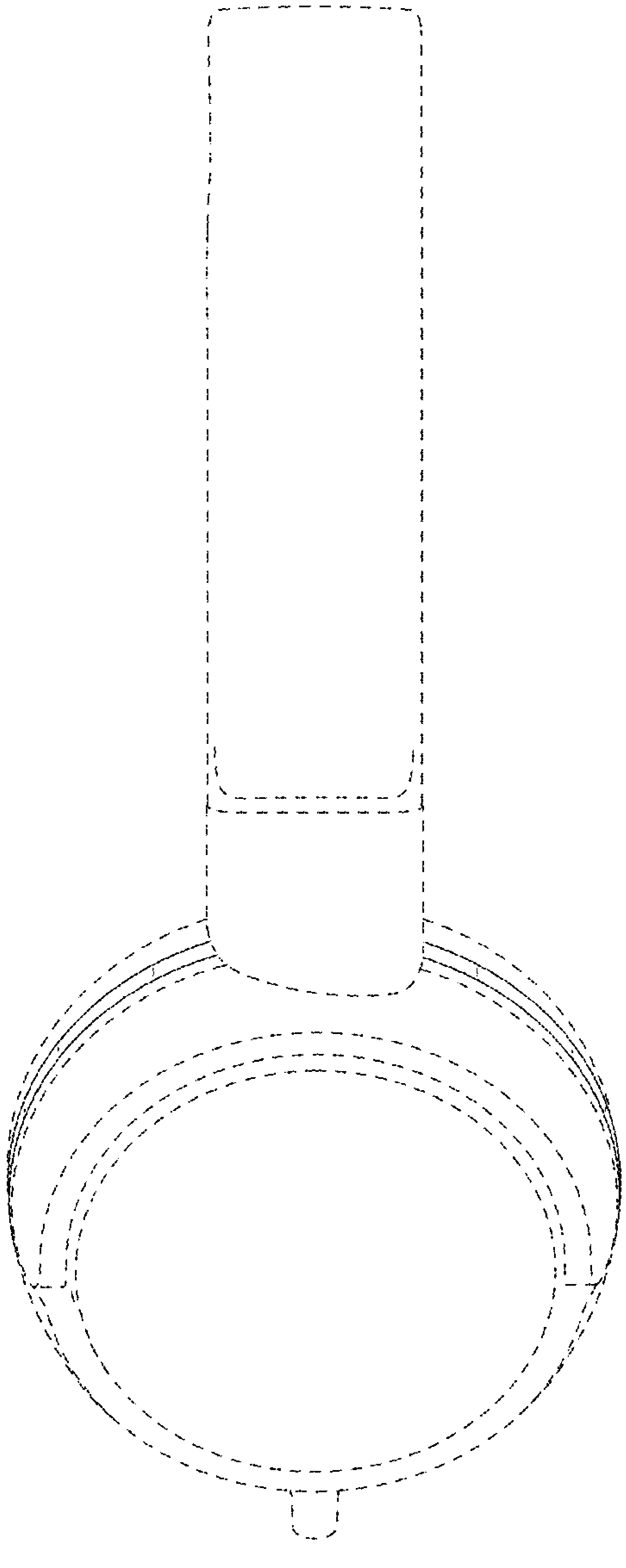

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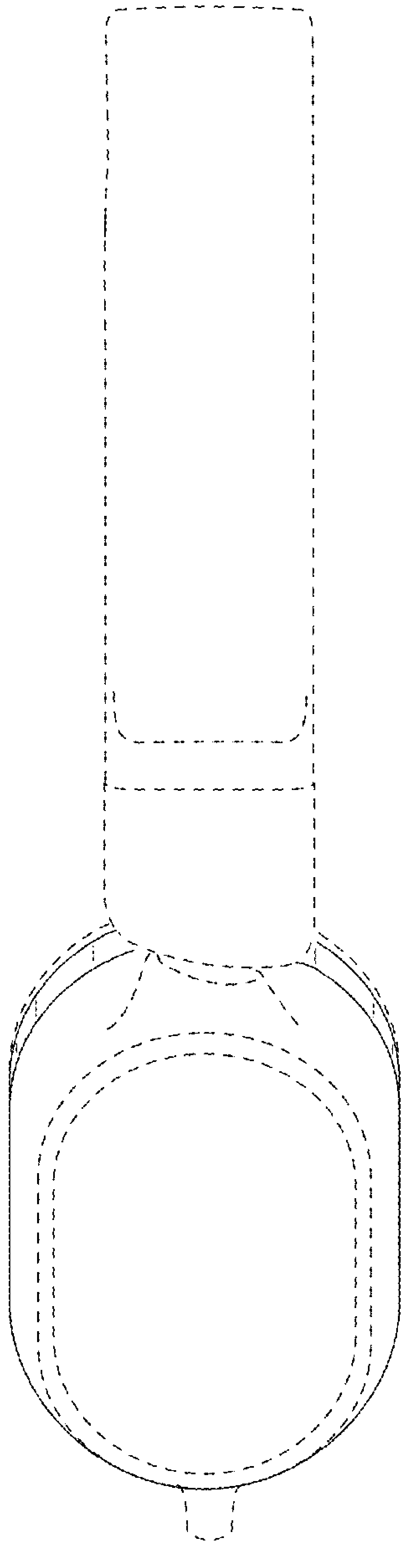

FIG.45